

CDX-605

SERVICE MANUAL

US Model



Model Name Using Similar Mechanism	CDX-505RF
CD Drive Mechanism Type	MG-250C-137
Optical Pick-up Name	KSS-521A/J2N

SPECIFICATIONS

System	Compact disc digital audio system
Frequency response	10 – 20,000 Hz
Wow and flutter	Below the measurable limit
Signal-to-noise ratio	94 dB
Outputs	BUS control output (8 pins) Analog audio output (RCA pin)
Current drain	800 mA (during CD playback) 800 mA (during loading or ejecting a disc)
Operating temperature	– 10 °C to + 55 °C (14 °F to 131 °F)
Dimensions	Approx. 262 × 90 × 181.5 mm (10 ³ / ₈ × 3 ⁵ / ₈ × 7 ¹ / ₄ in.) (w/h/d) not incl. projecting parts and controls
Mass	Approx. 2.1 kg (4 lb 10 oz)
Power requirement	12 V DC car battery (negative ground)
Supplied accessories	Disc magazine (1) Parts for installation and connections (1 set)

Design and specifications subject to change without notice.

COMPACT DISC CHANGER

SONY®



SECTION 1 SERVICING NOTES

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NOTES ON HANDLING THE OPTICAL PICK-UP BLOCK OR BASE UNIT

The laser diode in the optical pick-up block may suffer electrostatic breakdown because of the potential difference generated by the charged electrostatic load, etc. on clothing and the human body. During repair, pay attention to electrostatic breakdown and also use the procedure in the printed matter which is included in the repair parts.
The flexible board is easily damaged and should be handled with care.

Laser Diode Properties

- Material: GaAlAs
 - Wavelength: 780 nm
 - Emission Duration: continuous
 - Laser Output Power: less than 44.6 μW*
- * This output is the value measured at a distance of 200 mm from the objective lens surface on the Optical Pick-up Block.

CAUTION

Use of controls or adjustments or performance of procedures other than those specified herein may result in hazardous radiation exposure.

Flexible Circuit Board Repairing

- Keep the temperature of the soldering iron around 270 °C during repairing.
- Do not touch the soldering iron on the same conductor of the circuit board (within 3 times).
- Be careful not to apply force on the conductor when soldering or unsoldering.

Notes on chip component replacement

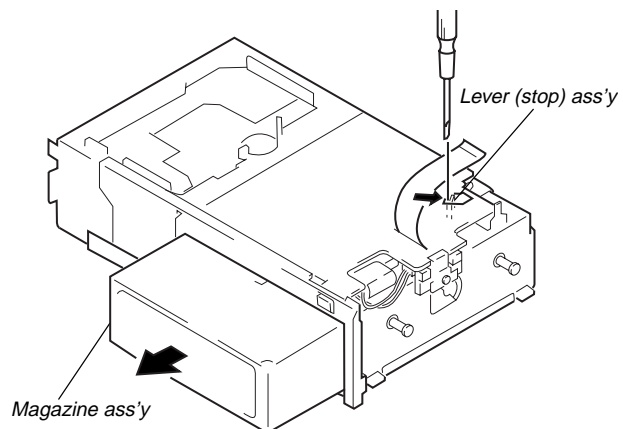
- Never reuse a disconnected chip component.
- Notice that the minus side of a tantalum capacitor may be damaged by heat.

DISC MAGAZINE GETTING OUT PROCEDURE ON THE POWER SUPPLY IS OFF

Remove the CASE (LOWER) assembly beforehand

- 1) Press the lever (stop) ass'y to arrow direction.
- 2) Removal the magazine ass'y.

Note: Take out the magazine only when the tray is completely within the magazine. If the disk or tray is sticking out, turn on the power and eject the magazine.



SAFETY-RELATED COMPONENT WARNING!!

COMPONENTS IDENTIFIED BY MARK \triangle OR DOTTED LINE WITH MARK \triangle ON THE SCHEMATIC DIAGRAMS AND IN THE PARTS LIST ARE CRITICAL TO SAFE OPERATION. REPLACE THESE COMPONENTS WITH SONY PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL OR IN SUPPLEMENTS PUBLISHED BY SONY.

SECTION 2
GENERAL

This section is extracted from instruction manual.

Installation

Precautions

- Choose the mounting location carefully, observing the following:
 - The unit is not subject to temperatures exceeding 55°C (131°F) (such as in a car parked in direct sunlight).
 - The unit is not subject to direct sunlight.
 - The unit is not subject to rain or moisture.
 - The unit is not exposed to excessive dust or dirt.
 - The unit is not exposed to excessive vibration.
 - The fast lank should not be damaged by the tapping screws.
 - There should be no hot surfaces or pipes under the place where you are going to install the unit.
 - The quarter, hood or other equipment in or under the trunk should not be interfered with or damaged by the screws or the unit itself.
 - Be sure to use only the supplied mounting hardware in a safe and secure installation.
 - Use only the supplied screws.

Installation

Précautions

- Choisir l'emplacement de montage en tenant compte des observations suivantes:
 - Appareil non soumis à des températures dépassant 55°C (131°F) (comme dans une voiture garée au soleil).
 - Appareil non soumis au rayonnement solaire direct.
 - Appareil à l'abri de sources de chaleur (comme des radiateurs).
 - Appareil non exposé à la pluie ou à l'humidité.
 - Appareil non exposé à des poussières ou à des saletés en excès.
 - Appareil non exposé à des vibrations excessives.
 - Vérifier que le revêtement d'essence ne risque pas d'être endommagé par les vis taraudeuses.
 - Il ne doit pas y avoir de pièces de fils ou de tuyaux à l'emplacement du montage.
 - Vérifier que l'appareil ou les vis ne risquent pas d'endommager ou de gêner le cuir ou le tapis, les sièges, ou autre objet dans le coffre.
 - Four garantir la sécurité de l'installation, utiliser uniquement le matériel de montage fourni.
 - Utiliser uniquement les vis fournies.

Instalación

Precauciones

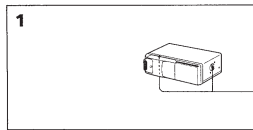
- Elija cuidadosamente el lugar de montaje y tenga en cuenta lo siguiente:
 - La unidad no queda sometida a temperaturas superiores a los 55°C (como en un automóvil estacionado a la luz solar directa).
 - La unidad no queda sometida a la luz solar directa.
 - La unidad no queda sujeta a fuertes lluvias (como aparatos de refrigeración).
 - La unidad no queda expuesta a la lluvia o a la humedad.
 - La unidad no queda sometida a polvo o suciedad excesivos.
 - La unidad no queda sometida a vibraciones excesivas.
 - El depósito de combustible no deberá dañarse con los tornillos automotrices.
 - No deberá haber masas de conductores ni tubos debajo del lugar donde vaya a instalar la unidad.
 - La funda de respuesta, las herramientas u otros equipos situados dentro o debajo del portaequipajes no deberán verse interferidos ni dañados por las tornillos de los propios aparatos.
 - Para realizar una instalación segura, emplee además la ferretería de montaje suministrada.
 - Utilice sólo los tornillos suministrados.

安裝

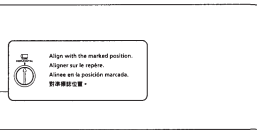
使用前的注意

- 請參照下列各項注意事項選擇安裝位置:
 - 機器不可暴露在超過 55°C 的溫度 (例如停放在太陽下的汽車內)。
 - 機器不可直接受到陽光。
 - 機器不可淋雨 (例如加冷器)。
 - 機器不可暴露在雨水或潮濕中。
 - 機器不可暴露在灰塵或污垢中。
 - 不要將機器安裝在電線或管線下方。
 - 小心別讓機器被雨水淋濕 (例如下雨)。
 - 小心別讓機器被灰塵或污垢所覆蓋。
 - 汽車燃料箱不應被螺絲釘損壞。
 - 行李架不應受到螺絲釘的損傷。上方若有其他設備的儲存位置不應受到機器安裝螺絲釘的干擾。
 - 為了完成安裝更安全可靠，請使用附帶的安裝工具。
 - 僅使用附帶的螺絲釘。

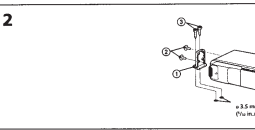
How to install the unit



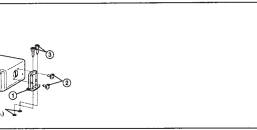
Installation de l'appareil



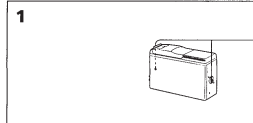
Instalación de la unidad



如何安裝機器



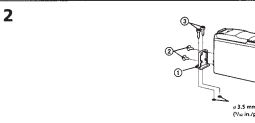
Vertical installation



Installation verticale



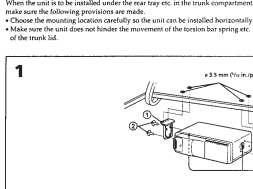
Instalación vertical



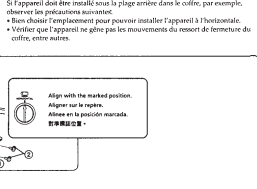
垂直安裝



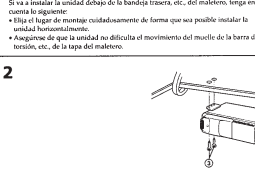
Suspended installation



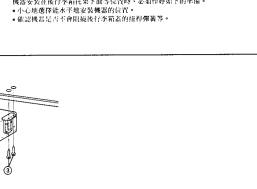
Installation suspendue



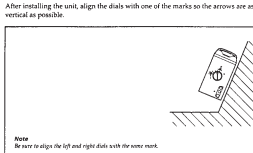
Instalación suspendida



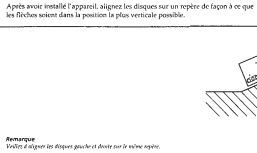
懸掛安裝



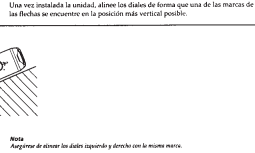
Inclined installation



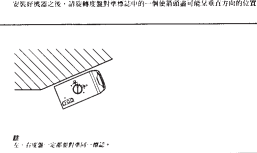
Installation inclinée



Instalación inclinada



傾斜安裝



Note

Be sure to align the left and right dials with the same mark.

Remarque

Vérifier d'aligner les disques gauche et droite sur la même repère.

Note

Asegure de alinear los diales izquierdo y derecho con la misma marca.

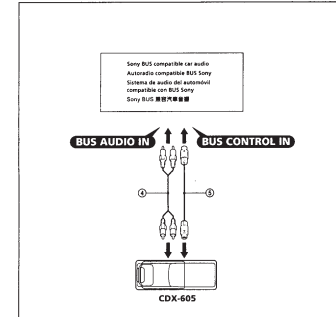
注意



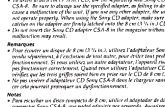
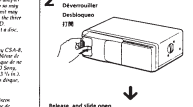
左右對準標記時，標記

Connections/Connexions/
Conexiones/ 連接

For detail, refer to the installation/Connections manual of the car audio.
Pour plus de détails, consultez le manuel d'installation/connexions de l'autoradio.
Con respecto a los detalles, consulte el manual de instalación/conexiones del sistema de audio del automóvil.
詳細請參照車載音響的安裝 / 連接說明。

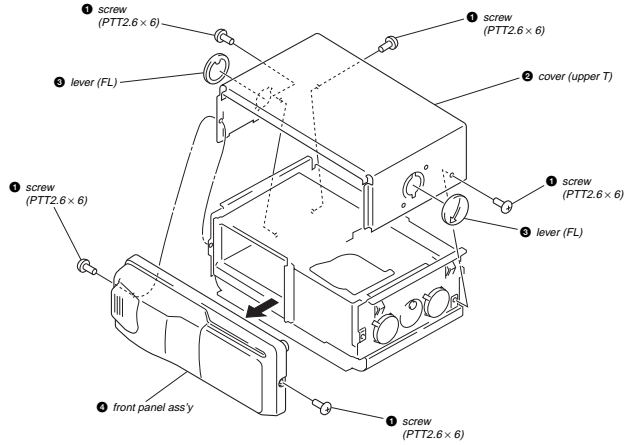
Connection diagram/ Schéma de connexions / Diagrama de conexión / 接線圖



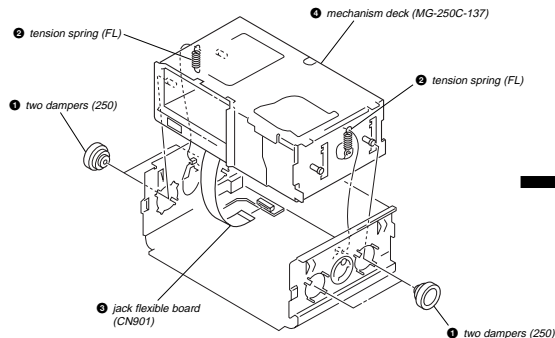
<p>Precautions Moisture condensation</p> <p>On a rainy day or in a very dusty area, moisture may condense on the lens inside the cap. Should the occur, the unit will not operate properly. In this case, remove the disc magazine and wait for about an hour until the moisture has evaporated.</p>	<p>Précautions Remarque sur la condensation d'humidité</p> <p>Pas temps pluvieux ou dans des régions très humides, de la condensation peut se former sur les lentilles de l'intérieur de l'appareil. Dans ce cas, l'appareil ne fonctionnera pas correctement. Retirez alors le chargeur de disques et attendez environ une heure jusqu'à ce que la condensation se soit évaporée.</p>	<p>Precauciones Condensación de humedad</p> <p>En los días lluviosos o en zonas muy húmedas, puede condensarse humedad en las lentes del interior de la unidad. Si esto ocurre, ésta no funcionará correctamente. En este caso, retire el cargador de discos y espere durante una hora aproximadamente hasta que la humedad se evapore.</p>	<p>使用前須注意 濕氣凝結</p> <p>若在多雨或非常潮濕的環境下，內部的鏡片可能會產生水氣凝結。在此情況下，機器將無法正常運作。在此情況下，請將碟片盒取出，並等待約一小時，讓水氣自然蒸發。</p>
<p>Inserting a disc</p> <p>1 With the arrow side facing up Avec la partie fléchée tournée vers le haut Con la flecha hacia arriba</p>  <p>Tab Disque Langspan</p> <p>Disc magazine Chargeur de disques</p> <p>Disc magazine does not lock properly Take out the magazine, and after pressing the EJECT button, reinsert it. Si vous ne pouvez pas fermer le chargeur de disques Sortez le chargeur de disques en appuyant sur la touche EJECT, réinsérez-le. Si el cargador de discos no se cierra correctamente Extraiga el cargador de discos y pulse el botón EJECT y vuelva a insertarlo.</p>	<p>Insertion d'un disque</p> <p>Labelled surface up Disques vers le haut Con la superficie de la etiqueta hacia arriba</p>  <p>10 discs, one in each tray 10 disques, un par plateau 10 discos, uno en cada bandeja</p> <p>Disc magazine Chargeur de disques</p> <p>Disc magazine does not lock properly Take out the magazine, and after pressing the EJECT button, reinsert it. Si vous ne pouvez pas fermer le chargeur de disques Sortez le chargeur de disques en appuyant sur la touche EJECT, réinsérez-le. Si el cargador de discos no se cierra correctamente Extraiga el cargador de discos y pulse el botón EJECT y vuelva a insertarlo.</p>	<p>Insertión de discos</p> <p>Labelled surface up Disques vers le haut Con la superficie de la etiqueta hacia arriba</p>  <p>10 discs, one in each tray 10 disques, un par plateau 10 discos, uno en cada bandeja</p> <p>Disc magazine Chargeur de disques</p> <p>Disc magazine does not lock properly Take out the magazine, and after pressing the EJECT button, reinsert it. Si vous ne pouvez pas fermer le chargeur de disques Sortez le chargeur de disques en appuyant sur la touche EJECT, réinsérez-le. Si el cargador de discos no se cierra correctamente Extraiga el cargador de discos y pulse el botón EJECT y vuelva a insertarlo.</p>	<p>裝入一張碟</p> <p>2</p> <p>Labelled surface up Disques vers le haut Con la superficie de la etiqueta hacia arriba</p>  <p>10 discs, one in each tray 10 disques, un par plateau 10 discos, uno en cada bandeja</p> <p>Disc magazine Chargeur de disques</p> <p>Disc magazine does not lock properly Take out the magazine, and after pressing the EJECT button, reinsert it. Si vous ne pouvez pas fermer le chargeur de disques Sortez le chargeur de disques en appuyant sur la touche EJECT, réinsérez-le. Si el cargador de discos no se cierra correctamente Extraiga el cargador de discos y pulse el botón EJECT y vuelva a insertarlo.</p>
<p>Notes on the disc magazine</p> <p>Normally, the tray will not come out of the magazine. However, if they are pulled out of the magazine, it is easy to reinsert them.</p> <p>When the tray comes out Normally, the tray will not come out of the magazine. However, if they are pulled out of the magazine, it is easy to reinsert them.</p> <p>Si la bandeja se sale Normalement, les bandejas ne se salent pas. Cependant, si elles sont tirées, elles peuvent être réinsérées facilement.</p> <p>When the tray comes out Normally, the tray will not come out of the magazine. However, if they are pulled out of the magazine, it is easy to reinsert them.</p>	<p>Remarques sur le chargeur de disques</p> <p>Normalement, les bandejas ne se salent pas. Cependant, si elles sont tirées, elles peuvent être réinsérées facilement.</p> <p>When the tray comes out Normally, the tray will not come out of the magazine. However, if they are pulled out of the magazine, it is easy to reinsert them.</p> <p>Si la bandeja se sale Normalement, les bandejas ne se salent pas. Cependant, si elles sont tirées, elles peuvent être réinsérées facilement.</p>	<p>Notas sobre el cargador de discos</p> <p>Normalmente, las bandejas no se salen. Sin embargo, si se sacan, es fácil volver a insertarlas.</p> <p>When the tray comes out Normally, the tray will not come out of the magazine. However, if they are pulled out of the magazine, it is easy to reinsert them.</p> <p>Si la bandeja se sale Normalement, les bandejas ne se salent pas. Cependant, si elles sont tirées, elles peuvent être réinsérées facilement.</p>	<p>碟碟匣須知</p> <p>通常情況下，碟碟匣不會自行彈出。然而，如果您將其拉出碟碟匣，則很容易重新插入。</p> <p>碟碟匣彈出時 通常情況下，碟碟匣不會自行彈出。然而，如果您將其拉出碟碟匣，則很容易重新插入。</p>
<p>Notes on compact discs</p> <p>A dirty or defective disc may cause sound dropouts during playback. To enjoy optimum sound, handle the disc as follows.</p> <p>Do not expose discs to direct sunlight or heat Do not touch the disc surface with your fingers. Do not use a car parked in direct sunlight where there can be considerable rise in the temperature inside the car.</p> <p>Before playing, clean the discs with an optical cleaning cloth. Wipe each disc in the direction of the arrows.</p> <p>Do not use solvents such as benzene, thinner, acetone or alcohol to clean discs or use the acetone spray intended for audio discs.</p>	<p>Remarques sur les disques compacts</p> <p>Un disque sale ou défectueux peut provoquer des pertes de son pendant la lecture. Manipulez le disque par son bord et ne touchez pas sa surface non protégée.</p> <p>Do not expose discs to direct sunlight or heat Do not touch the disc surface with your fingers. Do not use a car parked in direct sunlight where there can be considerable rise in the temperature inside the car.</p> <p>Before playing, clean the discs with an optical cleaning cloth. Wipe each disc in the direction of the arrows.</p> <p>Do not use solvents such as benzene, thinner, acetone or alcohol to clean discs or use the acetone spray intended for audio discs.</p>	<p>Notas sobre discos compactos</p> <p>Un disco sucio o defectuoso puede producir interrupciones de sonido durante la reproducción. Para disfrutar de una calidad de sonido óptima, manipule el disco de la siguiente manera.</p> <p>Do not expose discs to direct sunlight or heat Do not touch the disc surface with your fingers. Do not use a car parked in direct sunlight where there can be considerable rise in the temperature inside the car.</p> <p>Before playing, clean the discs with an optical cleaning cloth. Wipe each disc in the direction of the arrows.</p> <p>Do not use solvents such as benzene, thinner, acetone or alcohol to clean discs or use the acetone spray intended for audio discs.</p>	<p>雷射碟須知</p> <p>雷射碟若髒污或損壞，可能會導致播放時出現音質中斷。為了享受最佳音質，請按下列方法處理雷射碟。</p> <p>請勿將雷射碟直接暴露在陽光或熱度下 請勿用手指觸摸雷射碟表面 請勿將雷射碟放在陽光直射且車內溫度可能大幅上升的停車位</p> <p>播放前，請用光學清潔布清潔雷射碟。沿箭頭方向擦拭每片雷射碟。</p> <p>請勿使用苯、稀釋劑、丙酮或酒精等溶劑清潔雷射碟，或對雷射碟噴灑專用於音碟的丙酮噴霧。</p>

**SECTION 3
DISASSEMBLY**

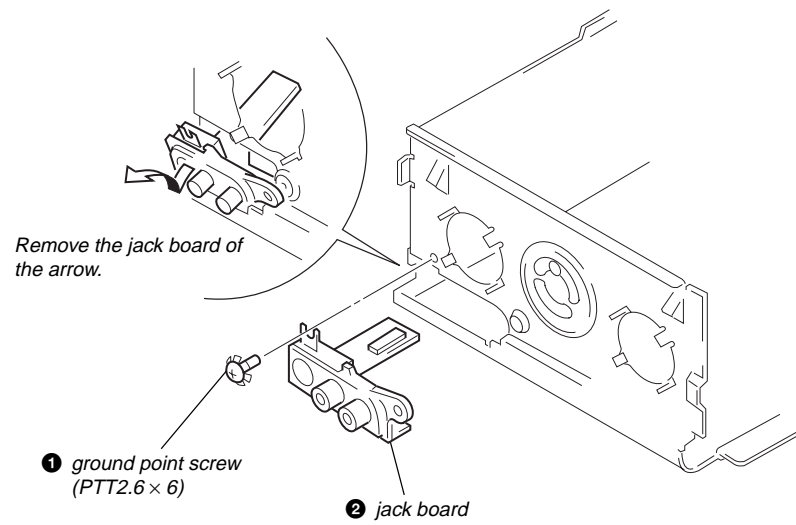
Note: Follow the disassembly procedure in the numerical order given.
COVER (UPPER T), FRONT PANEL ASS'Y



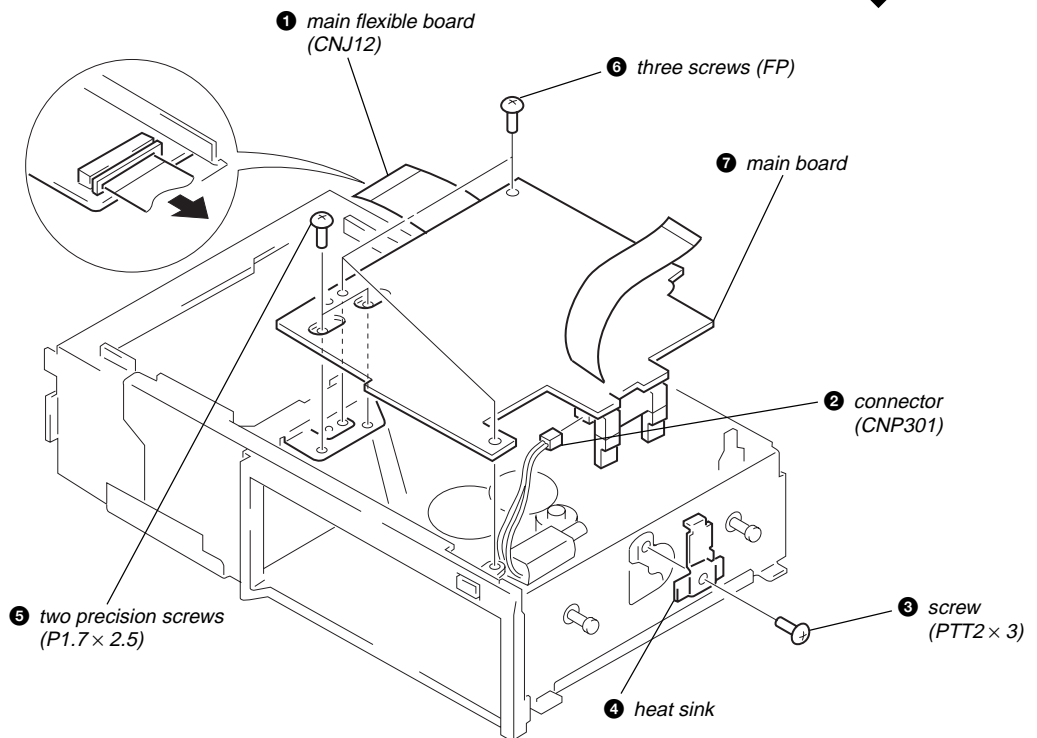
MECHANISM DECK (MG-250C-137)



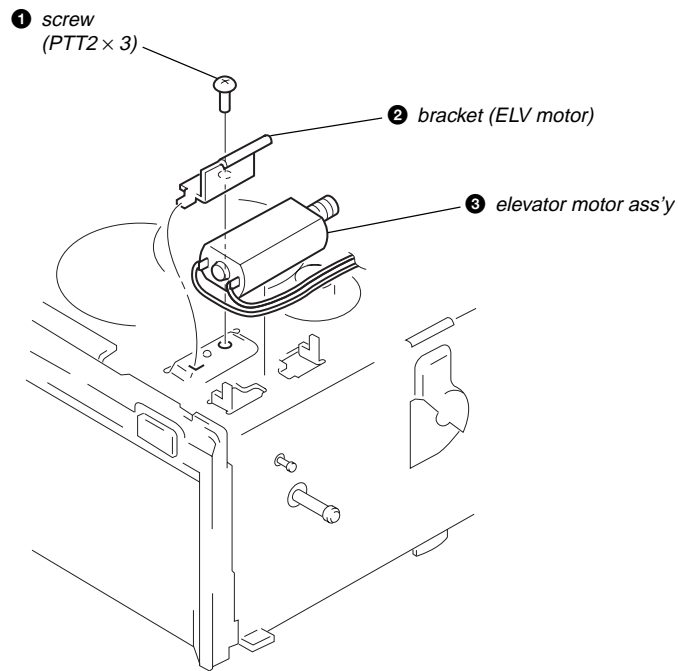
JACK BOARD



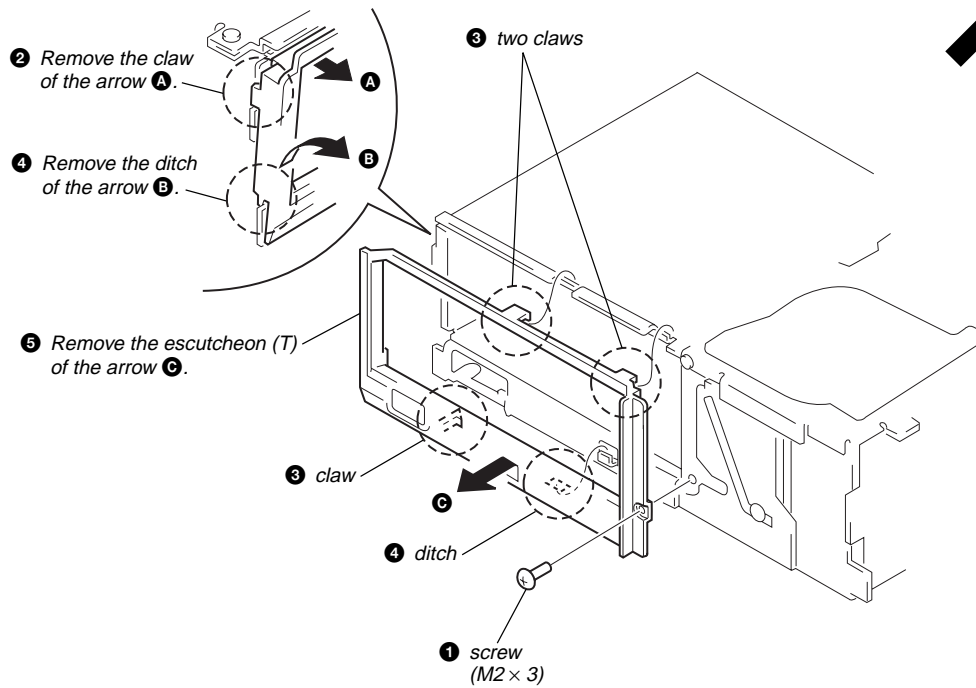
MAIN BOARD



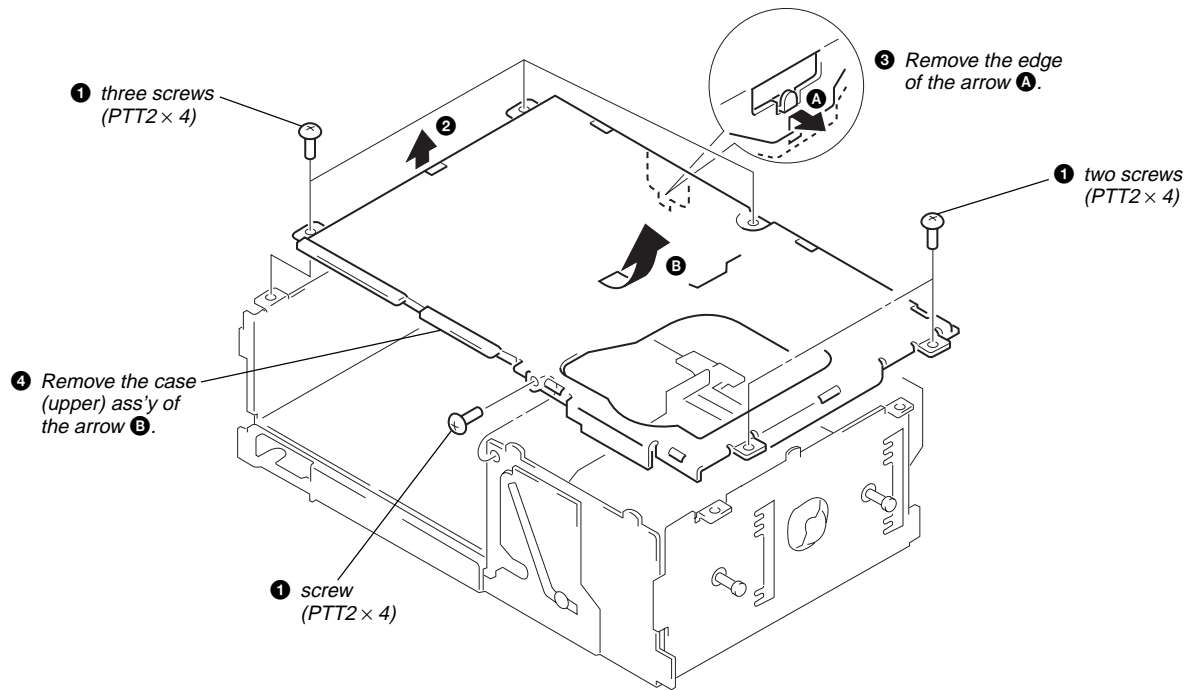
ELEVATOR MOTOR ASS'Y (M104)



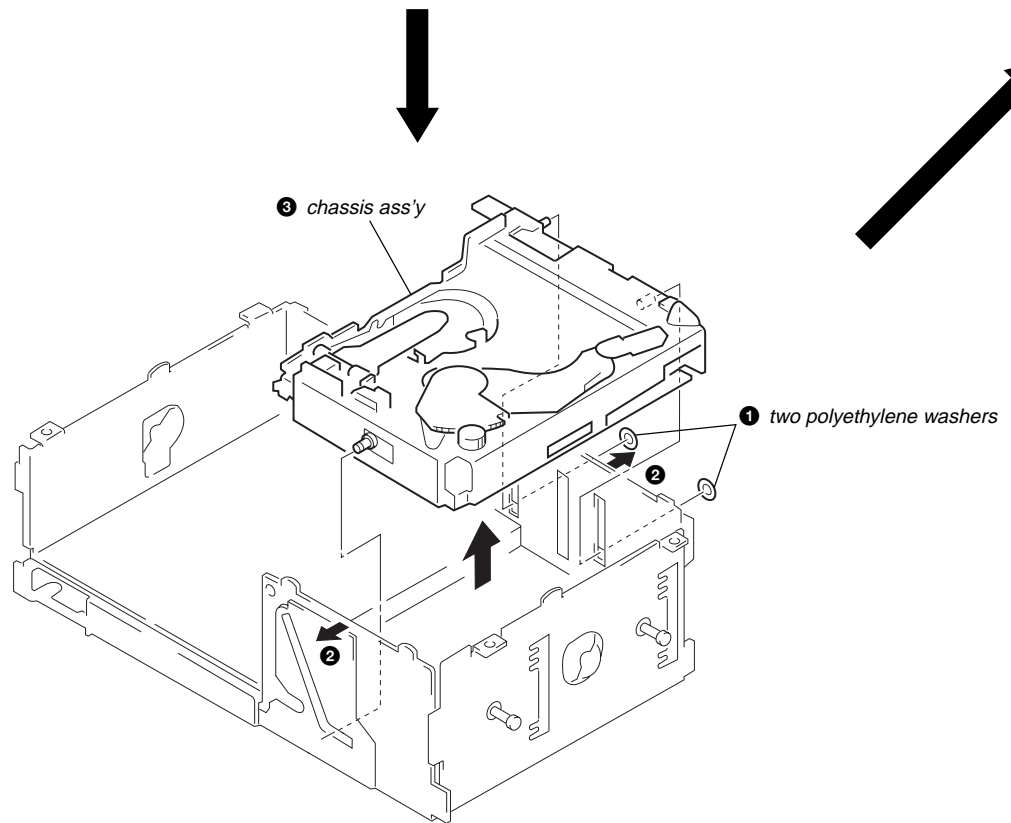
ESCUTCHEON (T)



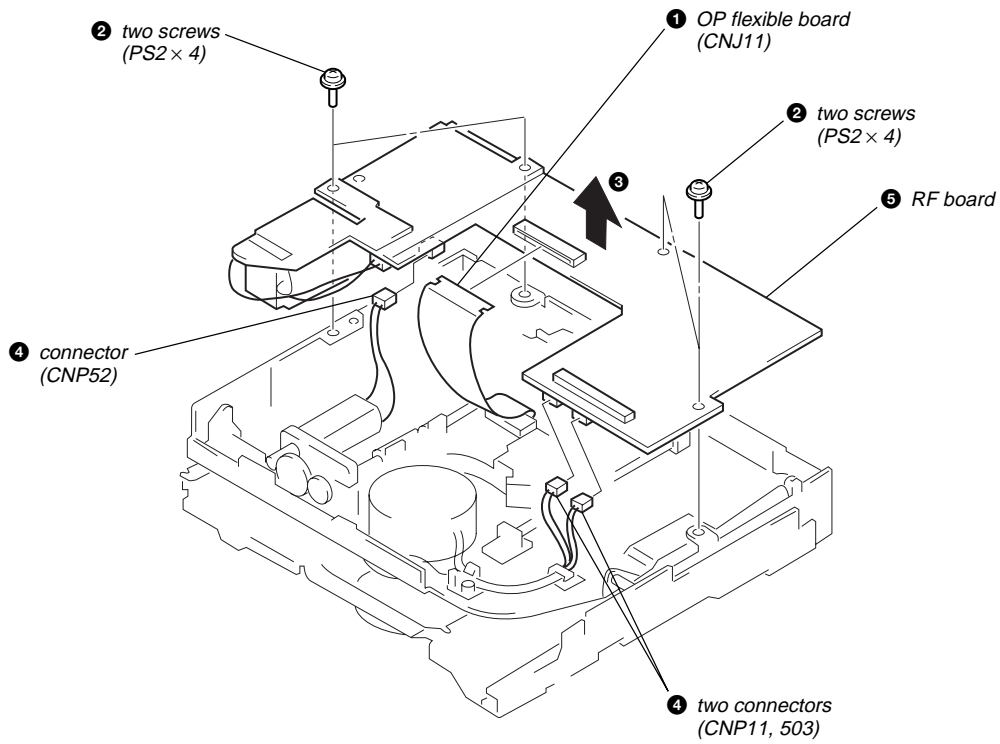
CASE (UPPER) ASS'Y



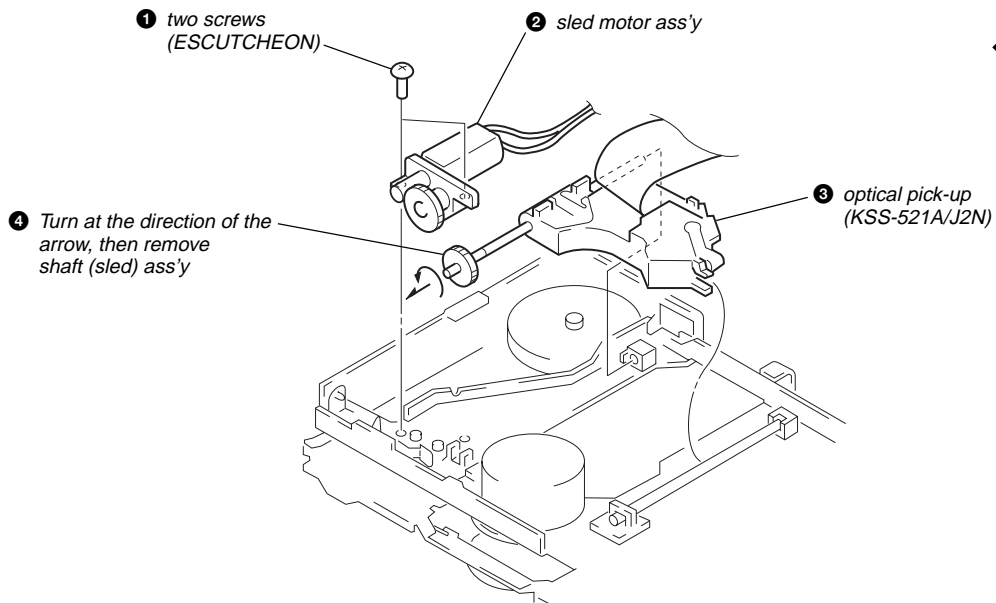
CHASSIS ASS'Y



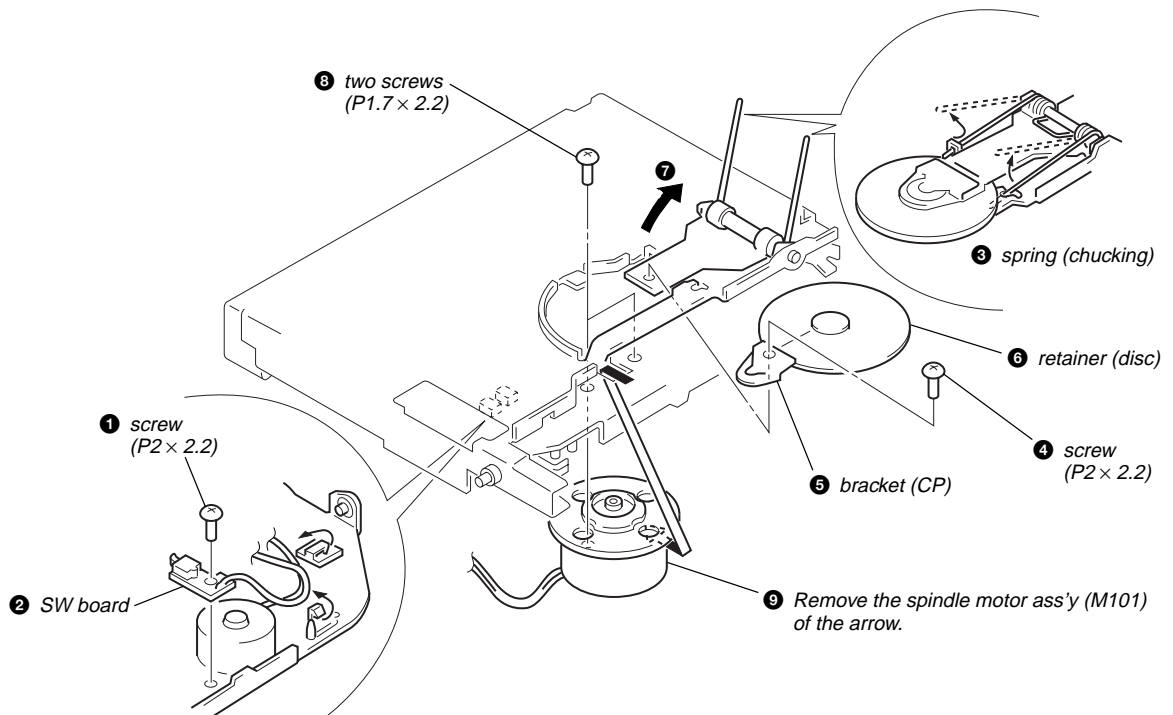
RF BOARD



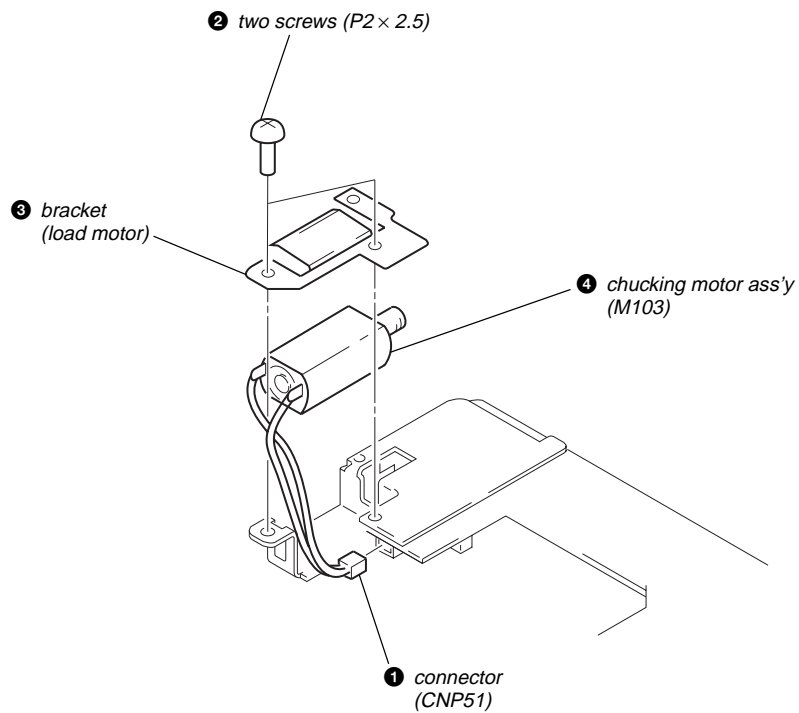
SLED MOTOR ASS'Y (M102), OPTICAL PICK-UP (KSS-521A/J2N)



SW BOARD, SPINDLE MOTOR ASS'Y (M101)



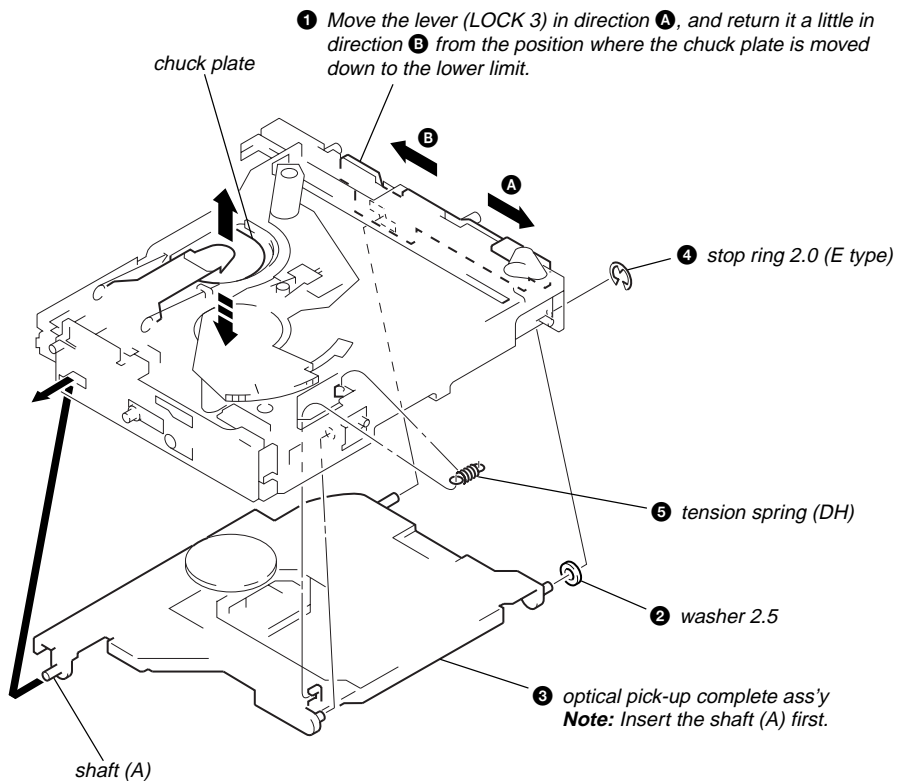
CHUCKING MOTOR ASS'Y (M103)



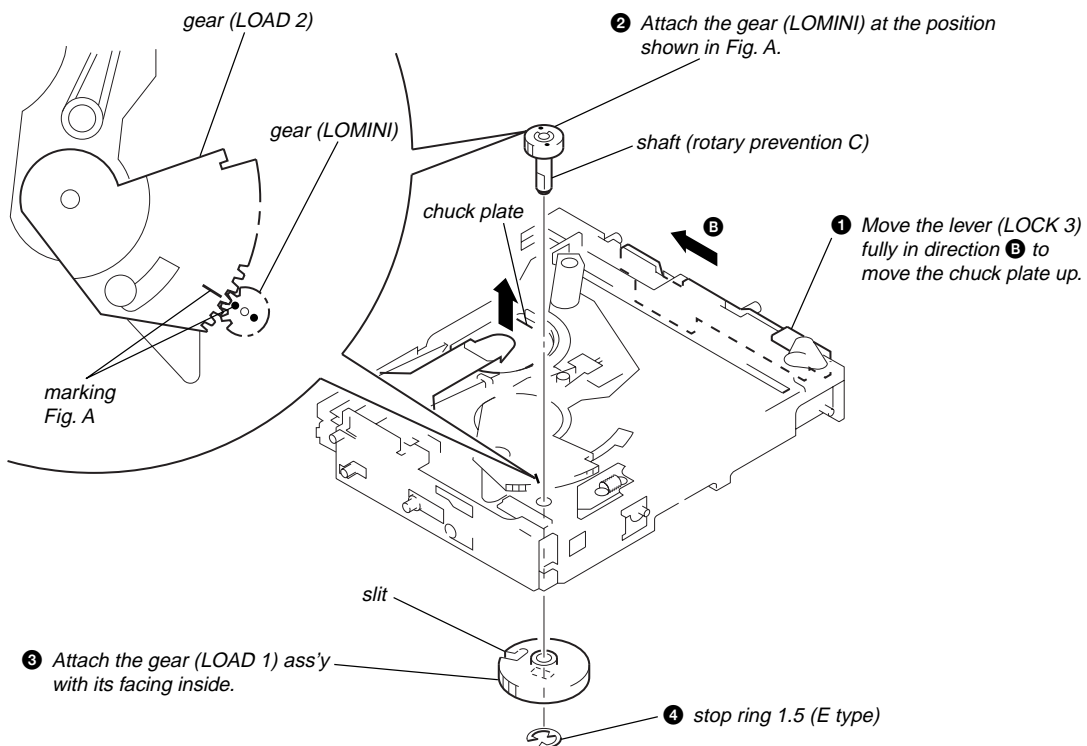
SECTION 4 MECHANISM DECK ASSEMBLY

Note: Follow the assembly procedure in the numerical order given.

OPTICAL PICK-UP COMPLETE ASS'Y

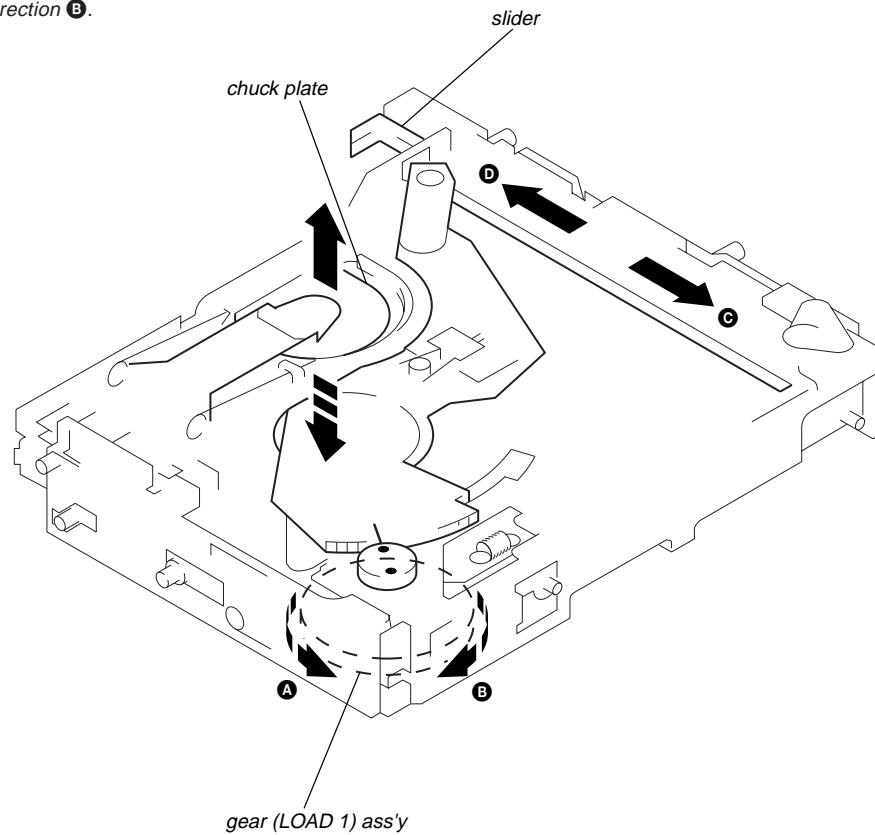


GEAR (LOMINI) / (LOAD 1) ASS'Y



OPERATION CHECK

- 1 Confirm that the slider moves in direction **C** to move down the chuck plate if the gear (LOAD 1) is rotated in direction **A** or the chuck plate moves up and the slider moves in direction **D** if the gear is rotated in direction **B**.

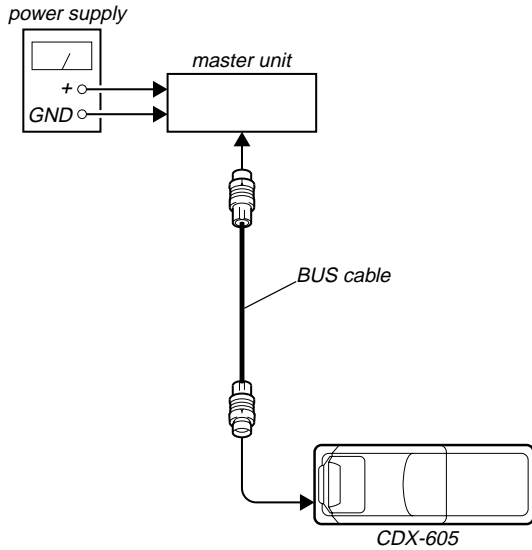


SECTION 5 MECHANICAL ADJUSTMENTS

• Elevator Height (Address) Adjustment

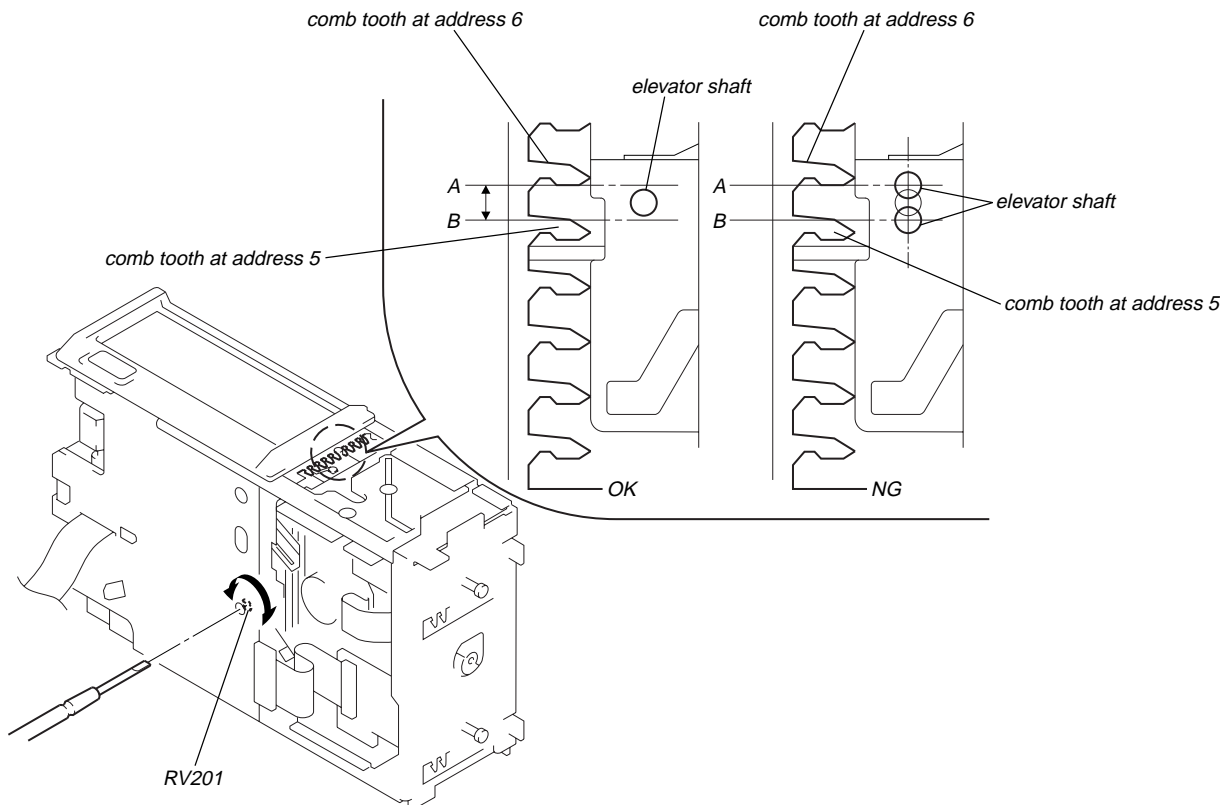
Note: This adjustments is necessary when the system controller (IC201), variable resistor (RV201), slider (R), slider (L), or chassis (ELV) was replaced for any repair.

Connection:



Adjustment Method:

1. Connect this set to the master unit (e.g. MDX-C670/ C670RDS), load a disc magazine, and place the set vertically as shown below.
2. Connect the regulated power supply to the master unit, and turn the power on.
3. Press the DISC button on the master unit and select DISC 5.
4. At this time, if the elevator shaft does not position between comb teeth A and B at addresses 5 and 6 as shown below, adjust the following.
5. Press repeatedly the DISC + and – buttons on the master unit so that the elevator shafts moves from address 6 to address 5, or from 5 to 6. At this time, adjust RV201 on the main board so that the elevator shaft positions smoothly between comb teeth A and B.
6. Further, place the set horizontally and make same adjustment as mentioned above.
7. After adjustment at addresses 5 to 6 is finished, check all operations from addresses 1 to 10 with the set placed vertically and horizontally respectively to confirm that the elevator shaft positions in a range between comb teeth A to B.



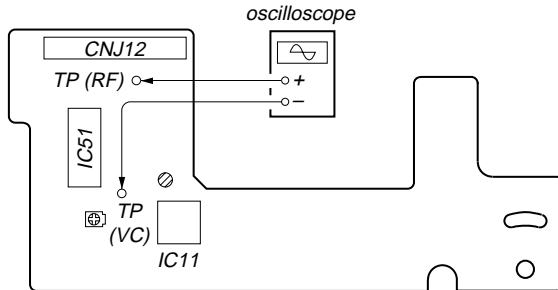
SECTION 6 ELECTRICAL ADJUSTMENTS

Note:

1. Perform adjustments as given.
2. Be sure to use the disc "YEDS-18" parts code: 3-702-101-01, but only when indicated.
3. Power supply voltage: DC14.4 V (more than 3A).

• FOCUS BIAS CHECK

[RF BOARD] – Conductor Side –



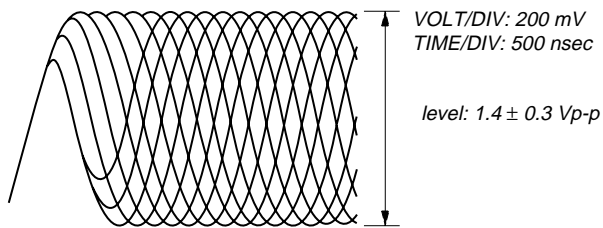
Procedure:

1. Connect the oscilloscope to RF board test point RF.
2. Put the set into play mode by loading the disc.
3. Confirm that oscilloscope waveform is clear and check RF signal level is correct or not.

Note:

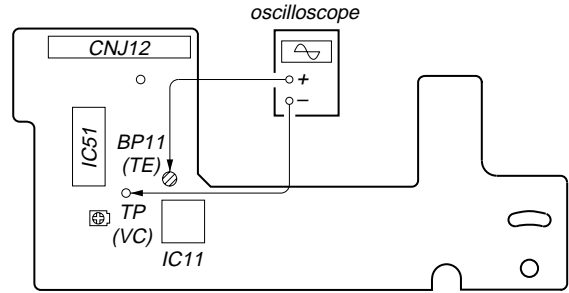
Clear RF signal waveform means that the shape "◇" can be clearly distinguished at the center of the waveform.

RF signal waveform



• TRACKING OFFSET CHECK

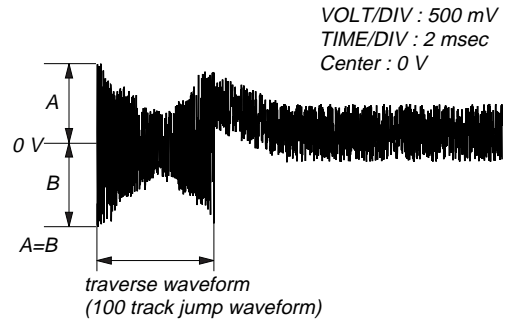
[RF BOARD] – Conductor Side –



Procedure:

1. Connect the oscilloscope to RF board bridge point TE.
2. Put the set into play mode by loading the disc.
3. Press the ◀◀ AMS ▶▶▶ button, then, check the traverse waveform.
4. Confirm that the oscilloscope waveform is symmetrical on the top and bottom in relation to 0 V dc, and check this level.

* Traverse waveform: This is the tracking error wave form appears when crossing the track.



• **FOCUS GAIN ADJUSTMENT
(COARSE ADJUSTMENT)**

This adjustment is to be performed when replacing the following parts.

- Optical Pick-up Block
- RV14

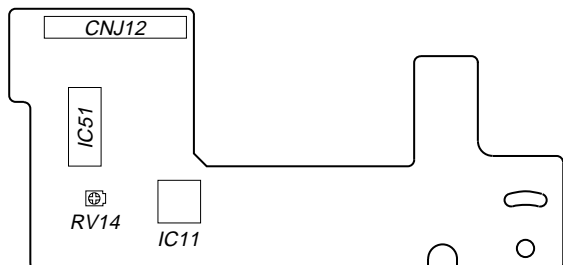
• **When gain is lowered...**

The set does not play because of no focus operation.

• **When gain is highered...**

Operation noise is heard due to a scratch or a dust, then operation will be unstable.

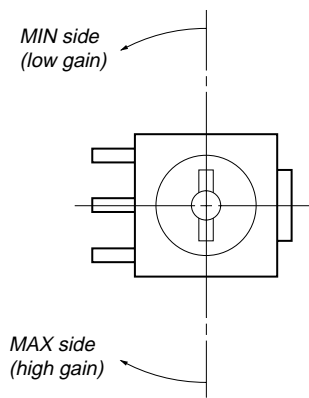
[RF BOARD] – Conductor Side –



Procedure:

1. Set RV14 (RF board) to the standard position.
2. Check that there is not an abnormal amount of operation noise (white noise) from the 2-axis devise. If there is, turn RV14 slightly clockwise.

[RF BOARD] – Conductor Side –

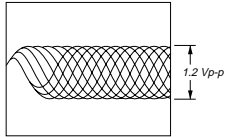


RV14 standard position

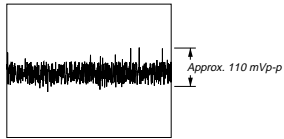
SECTION 7 DIAGRAMS

• Waveforms – RF Section –

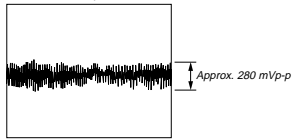
① IC11 (FEO)
500 mV/DIV, 500 nsec/DIV



② IC11 (FEI)
50 mV/DIV, 1 μsec/DIV

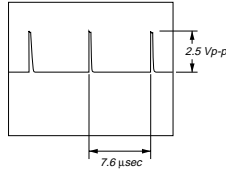


③ IC11 (TEI)
200 mV/DIV, 500 μsec/DIV

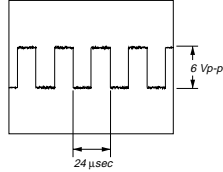


– MAIN Section –

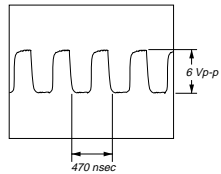
④ IC101 (MDP)



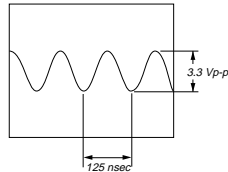
⑤ IC101 (LRCK)



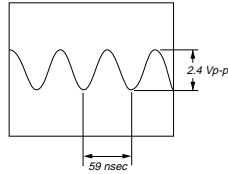
⑥ IC101 (BCK)



⑦ IC302 (EXTAL)



⑧ IC401 (XI)



7-1. NOTES FOR PRINTED WIRING BOARD AND SCHEMATIC DIAGRAM

Note on Schematic Diagram:

- All capacitors are in μF unless otherwise noted. pF: μF 50 WV or less are not indicated except for electrolytics and tantalums.
- All resistors are in Ω and $\frac{1}{4}\text{W}$ or less unless otherwise specified.
- Δ : internal component.
- \square : panel designation.

Note: The components identified by mark Δ , or dotted line with mark Δ , are critical for safety. Replace only with part number specified.

- $\text{B}+$: B+ Line.
- $\text{B}+$: adjustment for repair.
- Power voltage is dc 14.4V and fed from CD changer controller.
- Voltages and waveforms are dc with respect to ground in playback mode.
- Voltages are taken with a VOM (Input impedance 10 M Ω). Voltage variations may be noted due to normal production tolerances.
- Waveforms are taken with an oscilloscope. Voltage variations may be noted due to normal production tolerances.
- Signal path.
- \Rightarrow : CD

Note on Printed Wiring Board:

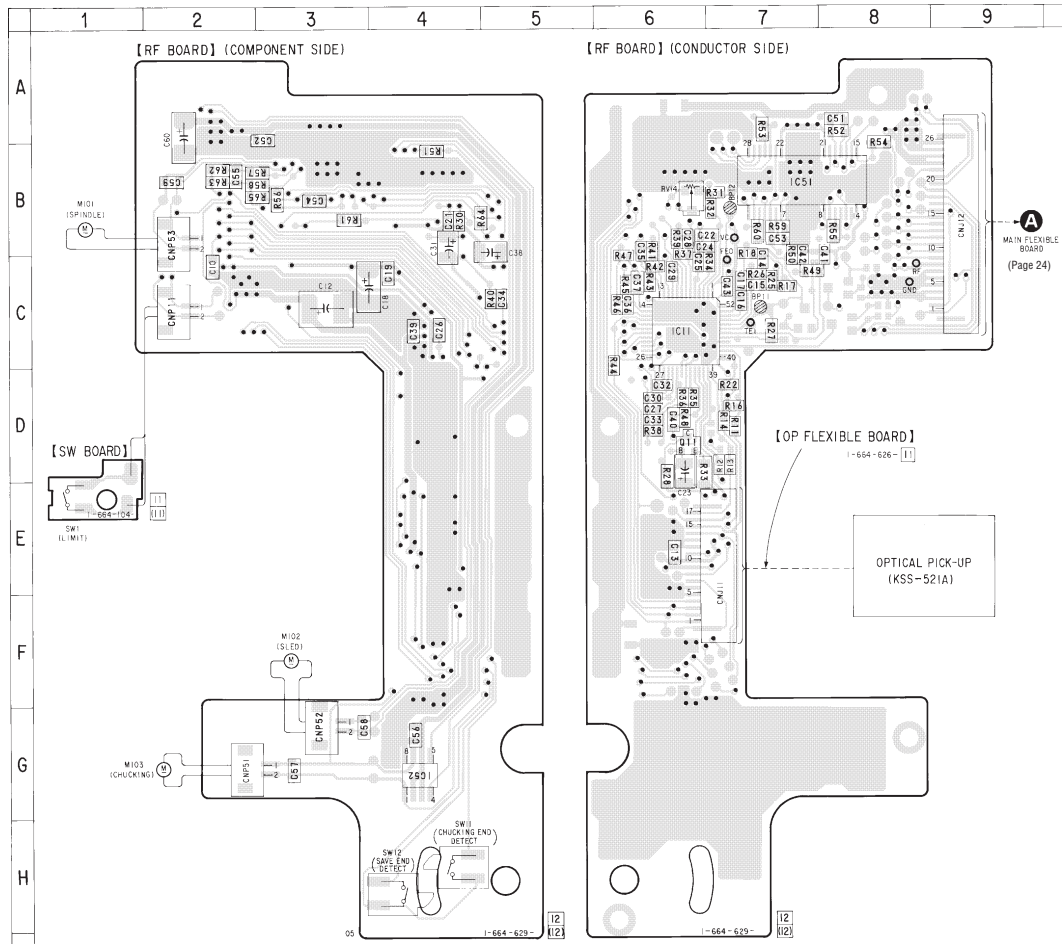
- \circ : parts extracted from the component side.
- \square : parts extracted from the conductor side.
- \bullet : Through hole.
- Δ : internal component.
- --- : Pattern from the side which enables seeing. (The other layers' patterns are not indicated.)

Caution:
 Pattern face side: Parts on the pattern face side seen from the pattern face are indicated.
 (Conductor Side)
 Parts face side: Parts on the parts face side seen from the parts face are indicated.
 (Component Side)

7-2. PRINTED WIRING BOARDS - RF Section -

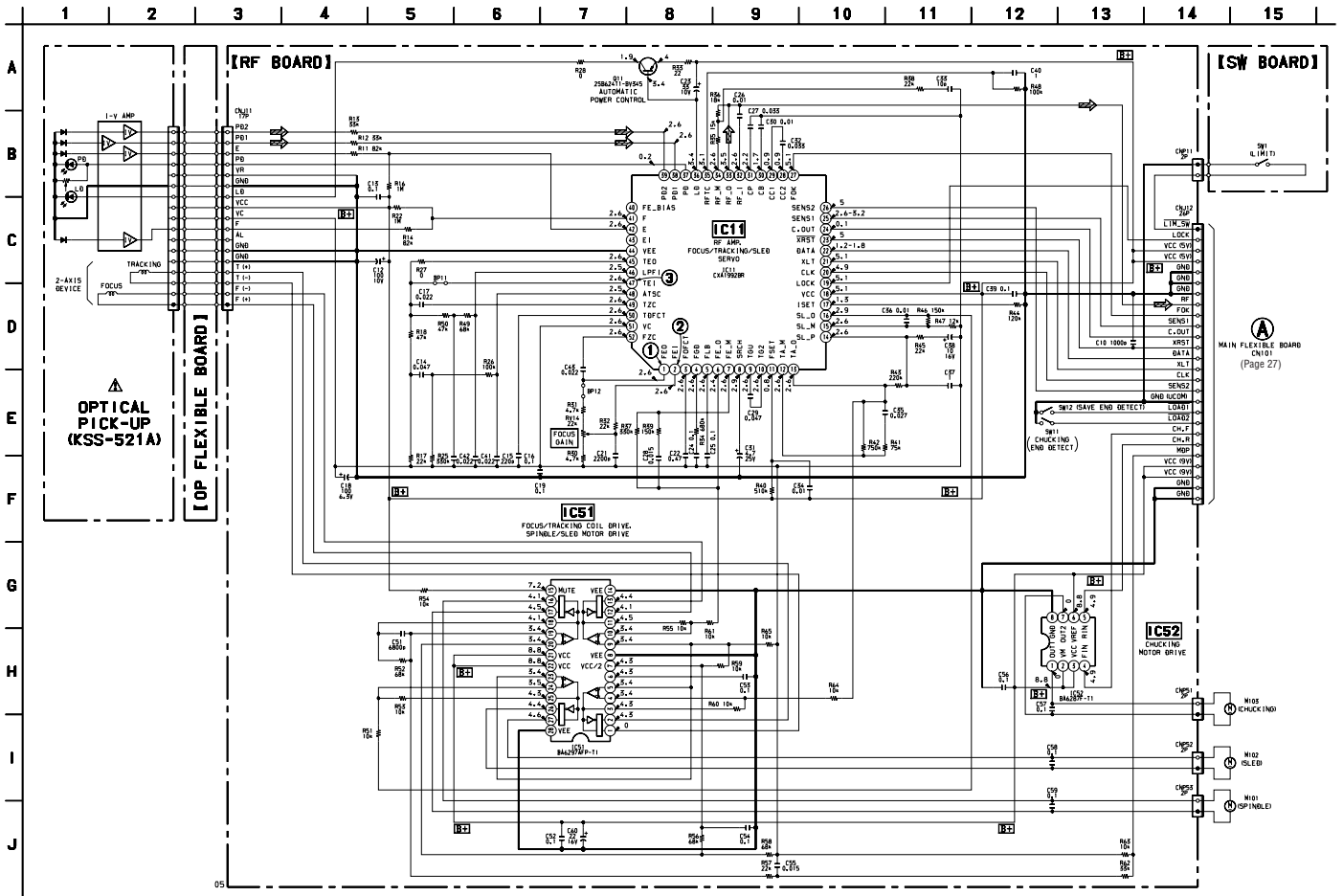
• Semiconductor Location

Ref. No.	Location
IC11	C-6
IC51	B-7
IC52	G-4
Q11	D-6



A
MAIN FLEXIBLE BOARD
(Page 24)

7-3. SCHEMATIC DIAGRAM - RF Section - • See page 17 for Waveforms. • See page 31 for IC Block Diagrams.

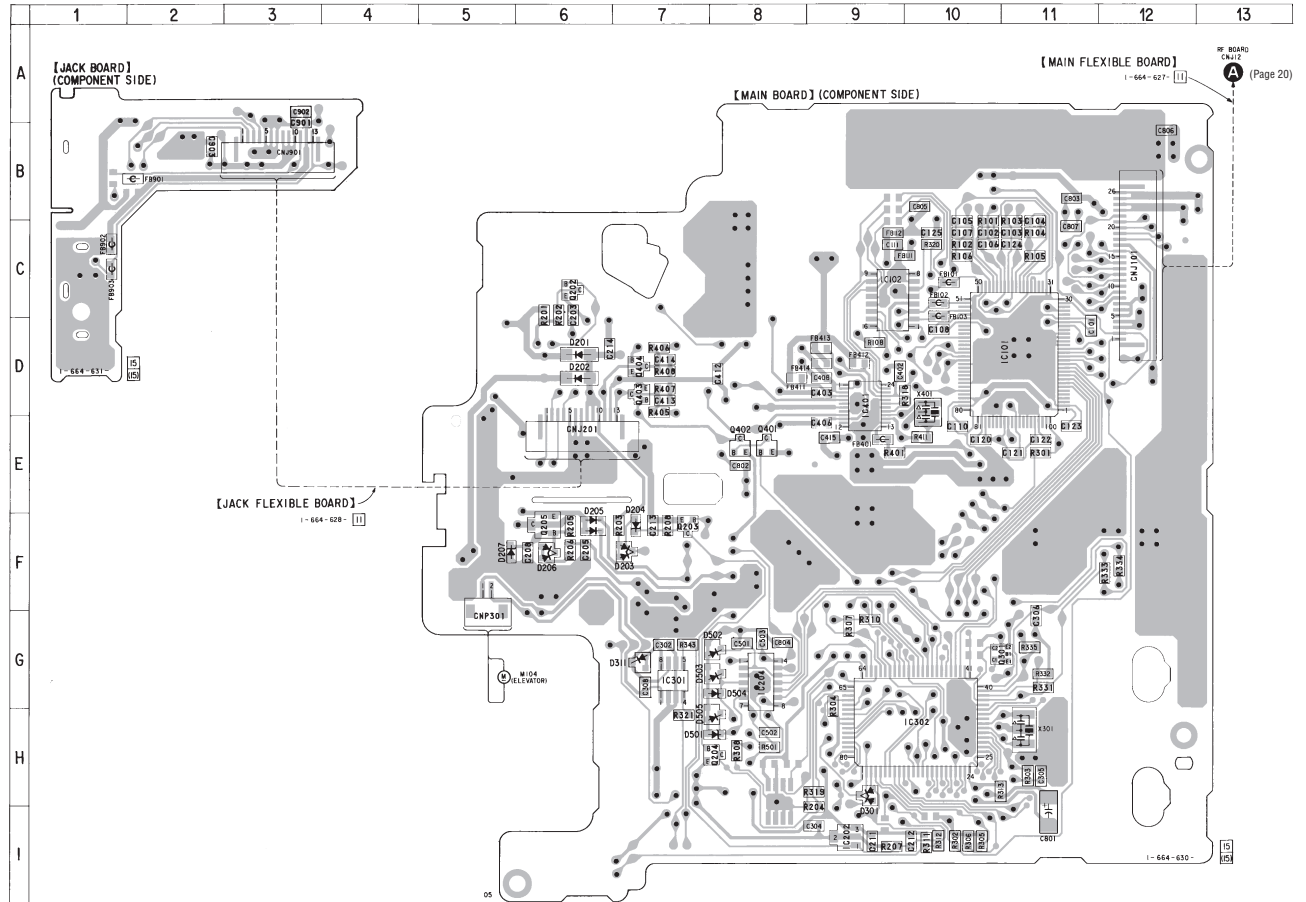


CDX-605

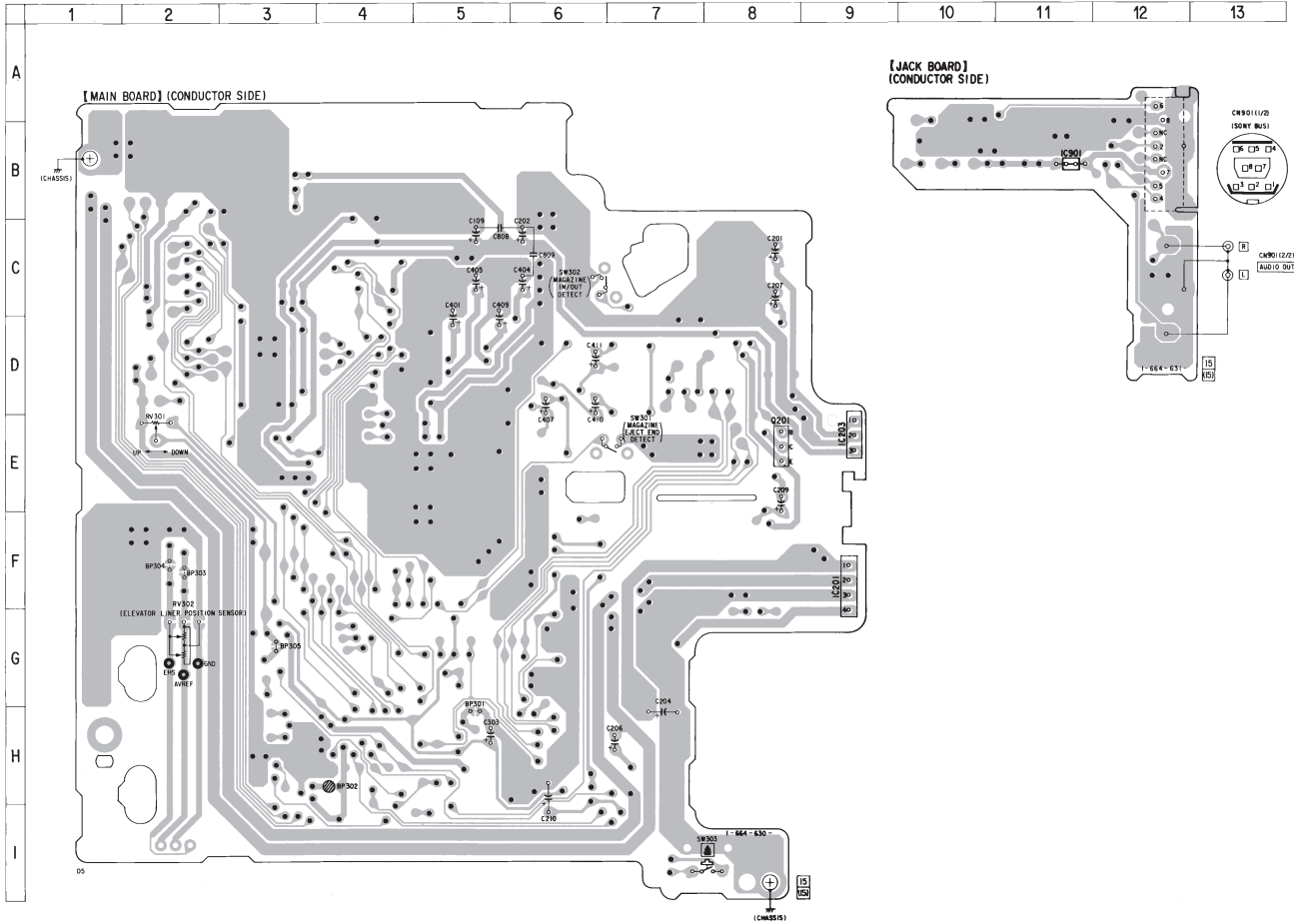
7-4. PRINTED WIRING BOARDS – MAIN/JACK BOARD (Component side) –

• Semiconductor Location

Ref. No.	Location
D201	D-6
D202	D-6
D203	F-7
D204	F-7
D205	F-6
D206	F-6
D207	F-5
D301	H-9
D311	G-7
D501	H-8
D502	G-8
D503	G-8
D504	G-8
D505	H-8
IC101	D-11
IC102	C-9
IC202	I-9
IC204	G-8
IC301	G-7
IC302	H-10
IC401	D-9
Q202	C-6
Q203	F-7
Q204	H-8
Q205	F-6
Q301	G-11
Q401	E-8
Q402	E-8
Q403	D-7
Q404	D-7

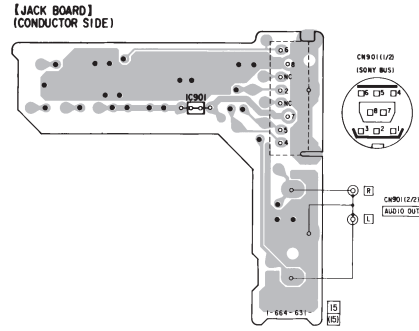


7-5. PRINTED WIRING BOARDS – MAIN/JACK BOARD (Conductor side) –

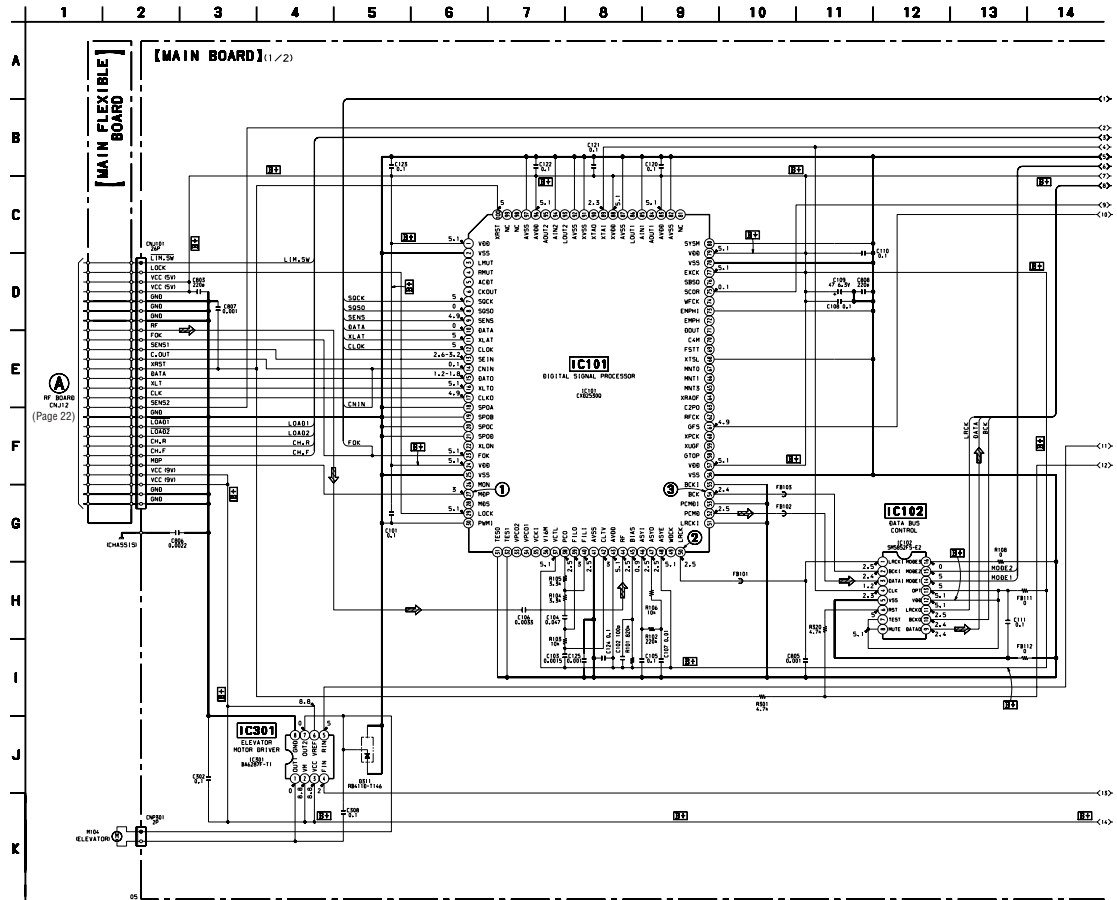


• Semiconductor Location

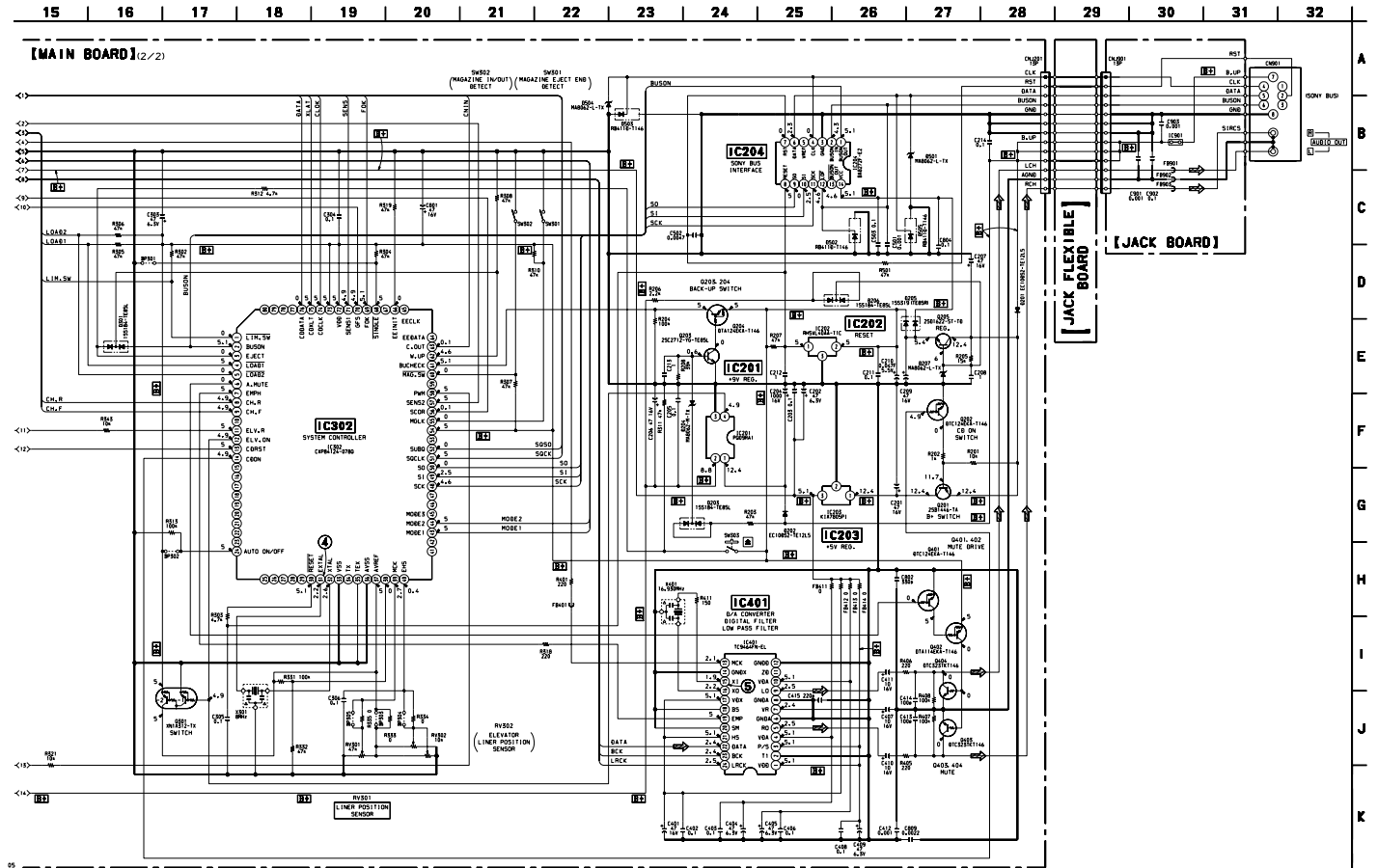
Ref. No.	Location
IC201	F-9
IC203	E-9
Q201	E-8



7-6. SCHEMATIC DIAGRAM – MAIN Section (1/2) – • See page 17 for Waveforms. • See page 31 for IC Block Diagrams.

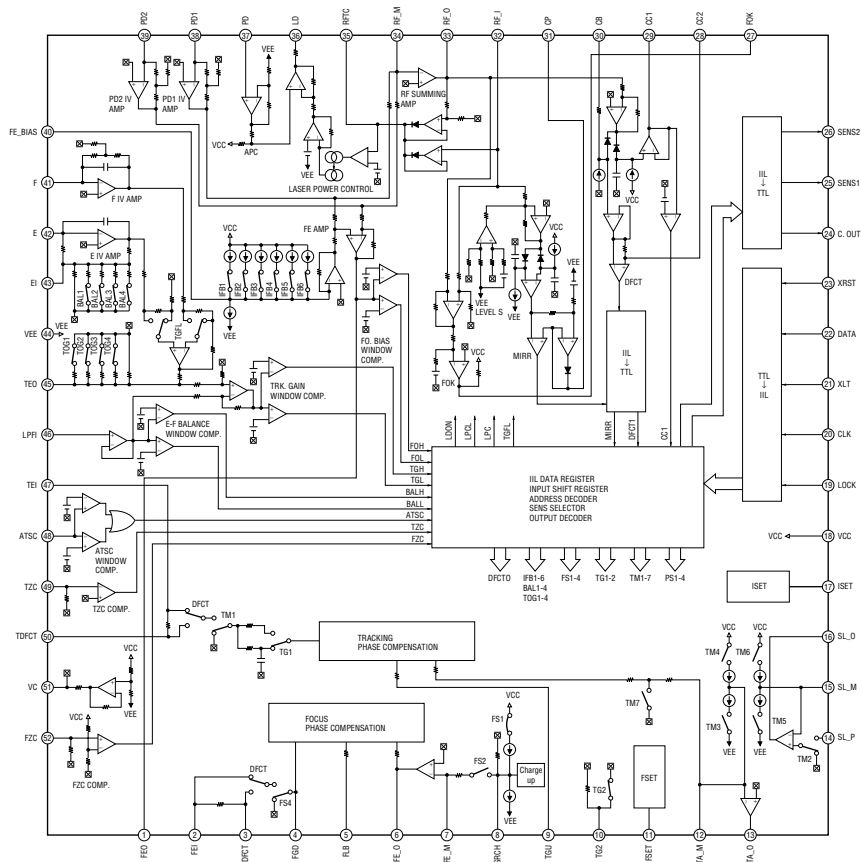


7-7. SCHEMATIC DIAGRAM - MAIN Section (2/2) - • See page 17 for Waveforms. • See page 31 for IC Block Diagrams.

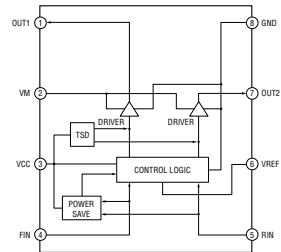


• IC Block Diagrams

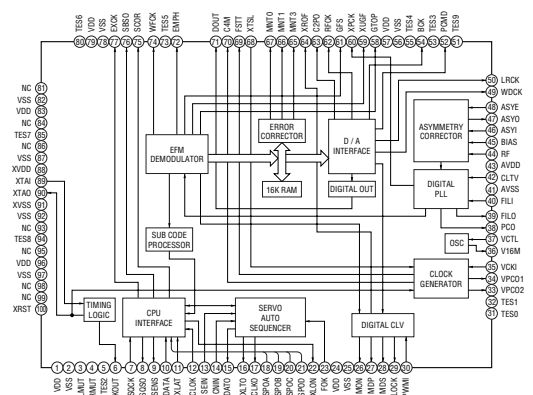
IC11 CXA1992BR (RF BOARD)



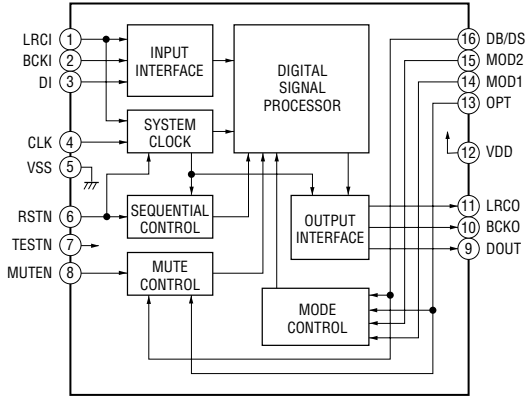
IC52 BA6287F (RF BOARD)
IC301 BA6287F (MAIN BOARD)



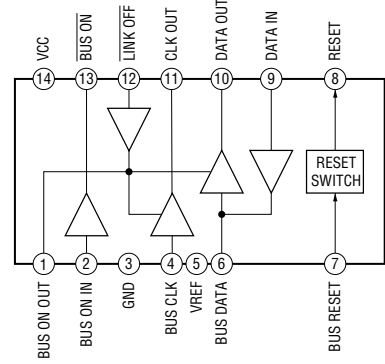
IC101 CXD2530Q (MAIN BOARD)



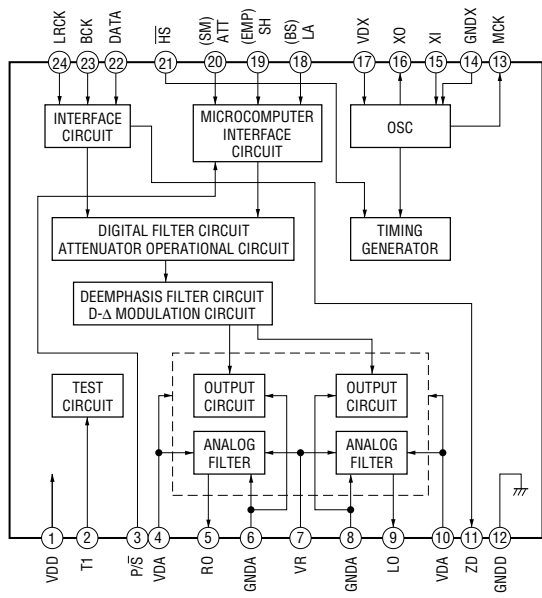
IC102 SM5852FS-E2 (MAIN BOARD)



IC204 BA8272F-E2 (MAIN BOARD)



IC401 TC9464FN-EL (MAIN BOARD)



7-8. IC PIN FUNCTION DESCRIPTION

• MAIN BOARD IC302 CXP84124-078Q (SYSTEM CONTROLLER)

Pin No.	Pin Name	I/O	Function
1	$\overline{\text{LIM.SW}}$	I	Sled limit in detect switch (SW1) input terminal “L”: When the optical pick-up is inner position
2	BUSON	I	Bus on/off control signal input from the SONY bus interface (IC204) “H”: bus on
3	EJECT	I	Eject switch (SW303) input terminal “H” active
4	$\overline{\text{LOAD1}}$	I	Save end detect switch (SW12) input terminal “L”: When completion of the disc chucking operation
5	$\overline{\text{LOAD2}}$	I	Chucking end detect switch (SW11) input terminal “L”: When completion of the disc chucking operation
6	A.MUTE	O	Audio line muting on/off control signal output terminal “H”: muting on
7	EMPH	O	Emphasis mode output to the D/A converter (IC401) “L”: emphasis on
8	CH.R	O	Motor drive signal (save direction) output to the chucking motor drive (IC52) “H” active *1
9	CH.F	O	Motor drive signal (load chucking direction) output to the chucking motor drive (IC52) “H” active *1
10	—	O	Not used (open)
11	ELV.R	O	Motor drive signal (elevator down direction) output to the elevator motor drive (IC301) “L” active *2
12	ELV.ON	O	Mechanism deck section power supply on/off control signal output “H”: power on
13	$\overline{\text{CD RST}}$	O	System reset signal output to the CXA1992AR (IC11), CXD2530Q (IC101) and SM5852FS (IC102) “L”: reset
14	CDON	O	D/A converter and servo section power supply on/off control signal output “H”: power on
15 to 23	—	O	Not used (open)
24	AUTO ON/OFF	I	Setting terminal for the automatic adjustment “L”: automatic adjustment, “H”: manual adjustment (solder across the BP302 terminal) Normally: fixed at “L”
25 to 29	—	O	Not used (open)
30	$\overline{\text{RESET}}$	I	System reset signal input from the reset signal generator (IC202) and SONY bus interface (IC204) “L”: reset For several hundreds msec. after the power supply rises, “L” is input, then it changes to “H”
31	EXTAL	I	Main system clock input terminal (8 MHz)
32	XTAL	O	Main system clock output terminal (8 MHz)
33	VSS	—	Ground terminal
34	TX	O	Sub system clock output terminal Not used (open)
35	TEX	I	Sub system clock input terminal Not used (fixed at “L”)
36	AVSS	—	Ground terminal (for A/D converter)
37	AVREF	I	Reference voltage (+5V) input terminal (for A/D converter)
38	ATRIBT	I	Selection input of the custom file, D-BASS, etc.
39	MCK	I	Input of signal for the fine adjustment (linear position sensor adjustment; RV301) of elevator position (A/D input)
40	EHS	I	Elevator height position detect input from the RV302 (elevator height sensor) (A/D input)
41	H.TEMP	I	High temperature sensor input terminal Not used (open)
42	—	O	Not used (open)
43	MODE1	O	D-BASS control signal output to the SM5852FS (IC102)
44	MODE2	O	D-BASS control signal output to the SM5852FS (IC102)
45	MODE3	O	D-BASS control signal output Not used (open)
46, 47	—	O	Not used (open)
48	SCK	I	Serial data transfer clock signal input from the SONY bus interface (IC204)
49	SI	I	Serial data input from the SONY bus interface (IC204)

Pin No.	Pin Name	I/O	Function
50	SO	O	Serial data output to the SONY bus interface (IC204)
51	SQCLK	O	Subcode Q data reading clock signal output to the CXD2530Q (IC101)
52	SUBQ	I	Subcode Q data input from the CXD2530Q (IC101)
53	—	O	Not used (open)
54	—	I	Not used (fixed at “H”)
55	MGLK	I	Magazine eject operation completion detect switch (SW301) input terminal “L”: eject completed
56	SCOR	I	Subcode sync (S0+S1) detection signal input from the CXD2530Q (IC101)
57	SENS2	I	Internal status signal (sense signal) input from the CXA1992AR (IC11)
58	PWM	O	Motor drive signal (elevator up direction) output to the elevator motor drive (IC301) “L” active *2
59	—	O	Not used (open)
60	MAG.SW	I	Magazine in/out detect switch (SW302) input terminal “L”: magazine detected
61	BUCHECK	I	Battery detection signal input terminal “H”: battery on
62	W.UP	I	Bus on or eject switch (SW303) input terminal “H”: bus on or eject switch pushing
63	C.OUT	I	Track number count signal input from the CXA1992AR (IC11)
64	EEDATA	I/O	Two-way data bus with the EEPROM Not used (open)
65	EECLK	O	Serial clock signal output to the EEPROM Not used (open)
66	EEINIT	I	Initialize signal input for the EEPROM “H”: format Fixed at “L” in this set
67	—	O	Not used (open)
68	SINGLE	I	Setting terminal for the single disc/multiple discs mode “L”: single mode, “H”: multiple discs mode (fixed at “H”)
69	FOK	I	Focus OK signal input from the CXA1992AR (IC11) “L”: NG, “H”: OK
70	GFS	I	Guard frame sync signal input from the CXD2530Q (IC101) “L”: NG, “H”: OK
71	SENS1	I	Internal status signal (sense signal) input from the CXD2530Q (IC101)
72	VDD	—	Power supply terminal (+5V)
73	NC (VDD)	—	Connected to the power supply (+5V)
74	CDCLK	O	Serial data transfer clock signal output to the CXD2530Q (IC101)
75	CDXLT	O	Serial data latch pulse signal output to the CXD2530Q (IC101)
76	CDDATA	O	Serial data output to the CXD2530Q (IC101)
77 to 80	—	O	Not used (open)

*1 chucking motor (M103) control

Terminal \ Mode	STOP	LOAD CHUCKING	SAVE	BRAKE
CH.F (pin ⑨)	“L”	“H”	“L”	“H”
CH.R (pin ⑩)	“L”	“L”	“H”	“H”

*2 elevator motor (M104) control

Terminal \ Mode	STOP	ELEVATOR UP	ELEVATOR DOWN	BRAKE
PWM (pin ⑤⑧)	“H”	“L”	“H”	“L”
ELV.R (pin ⑪)	“H”	“H”	“L”	“L”

SECTION 8 EXPLODED VIEWS

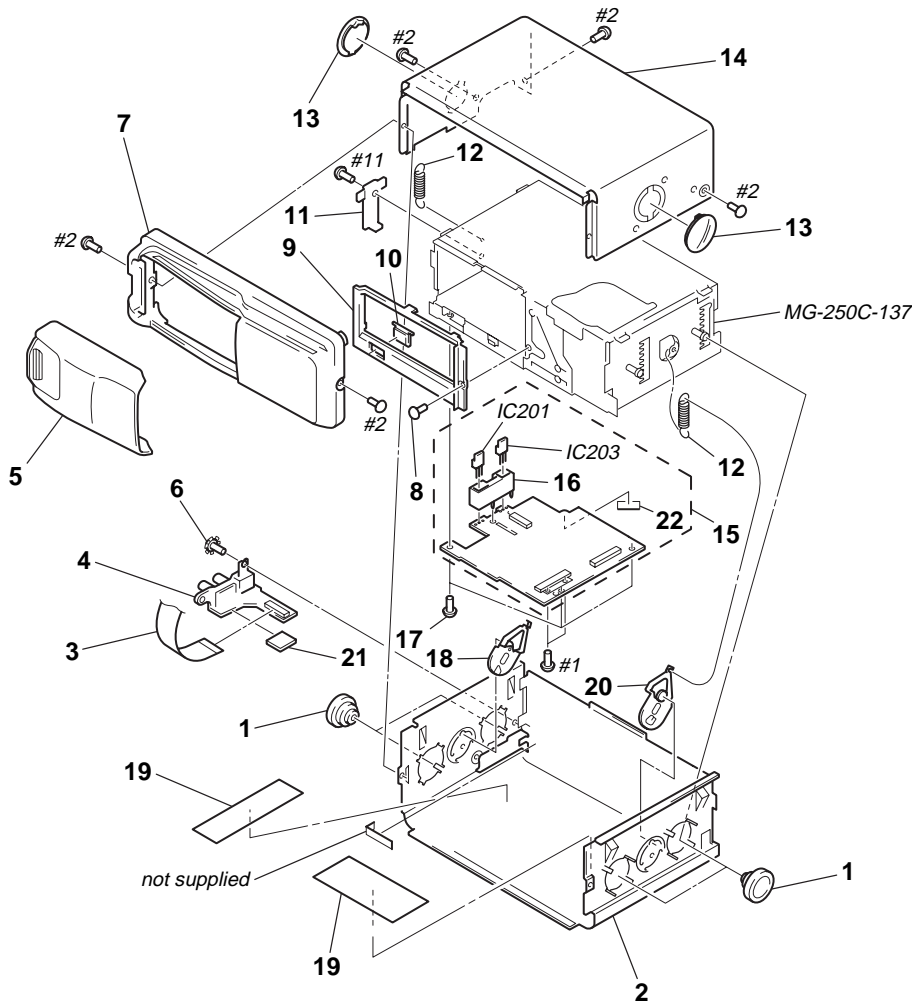
NOTE:

- -XX and -X mean standardized parts, so they may have some difference from the original one.
- Color Indication of Appearance Parts
Example:
KNOB, BALANCE (WHITE) . . . (RED)
 ↑ ↑
 Parts Color Cabinet's Color

- Items marked "***" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- The mechanical parts with no reference number in the exploded views are not supplied.
- Hardware (# mark) list and accessories and packing materials are given in the last of the electrical parts list.

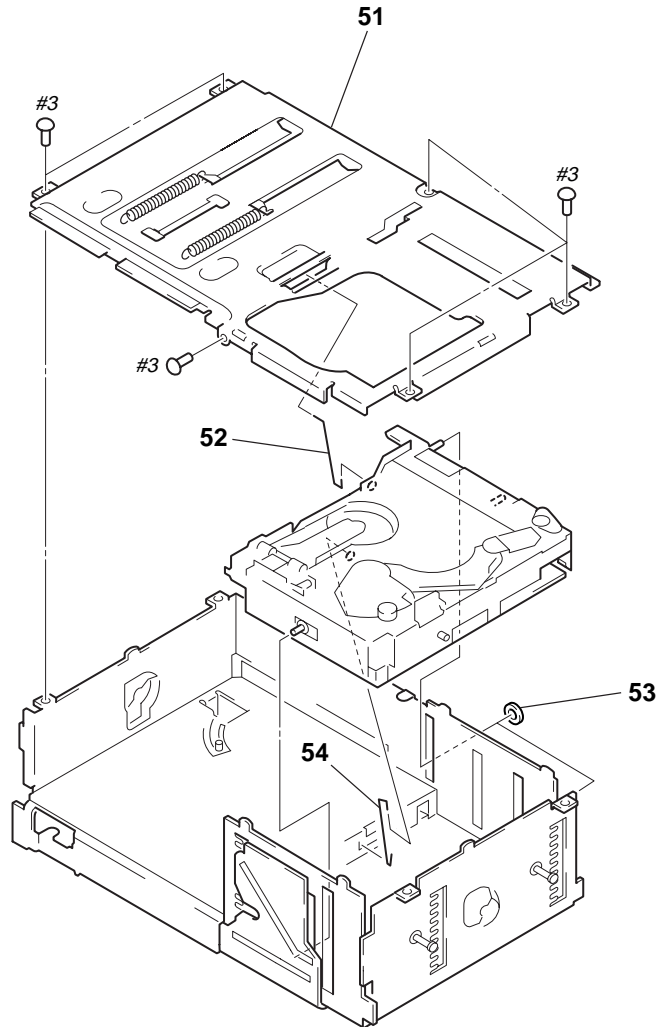
The components identified by mark \triangle or dotted line with mark \triangle are critical for safety. Replace only with part number specified.

(1) COVER SECTION



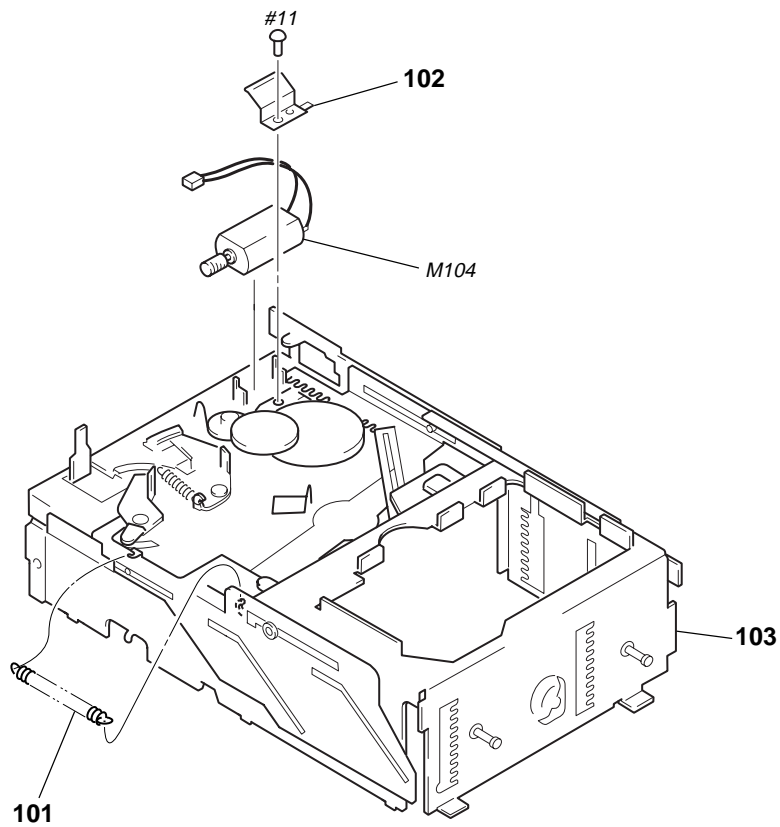
Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
1	3-010-104-01	DAMPER (250)		13	3-010-101-11	LEVER (FLT)	
* 2	3-010-097-41	COVER (LOWER)		* 14	3-010-096-41	COVER (UPPER)	
3	1-664-628-11	JACK FLEXIBLE BOARD		* 15	A-3317-257-A	MAIN BOARD, COMPLETE	
* 4	1-664-631-15	JACK BOARD		* 16	3-022-694-01	HOLDER (TR3)	
5	X-3375-359-2	DOOR (T) ASSY		17	3-935-636-11	SCREW (FP)	
6	3-376-464-11	SCREW (+PTT 2.6X6), GROUND POINT		18	X-3375-357-1	ARM (FLT) ASSY	
7	3-022-002-01	PANEL (T), FRONT		19	3-013-658-01	SHEET (FJT), PROTECTION	
8	3-012-388-01	SCREW (M2X3)		20	X-3375-360-1	ARM (FRT) ASSY	
9	3-022-006-01	ESCUTCHEON (T)		21	3-350-124-01	CUSHION (EJECT)	
10	3-022-007-01	BUTTON (EJT) (\blacktriangle)		* 22	3-016-116-01	TAPE (D), MOUNT	
* 11	3-022-012-01	HEAT SINK (T)		IC201	8-759-054-12	IC PQ09RA1	
12	3-010-103-01	SPRING (FL), TENSION		IC203	8-759-324-40	IC KIA7805PI	

**(2) MECHANISM DECK SECTION-1
(MG-250C-137)**



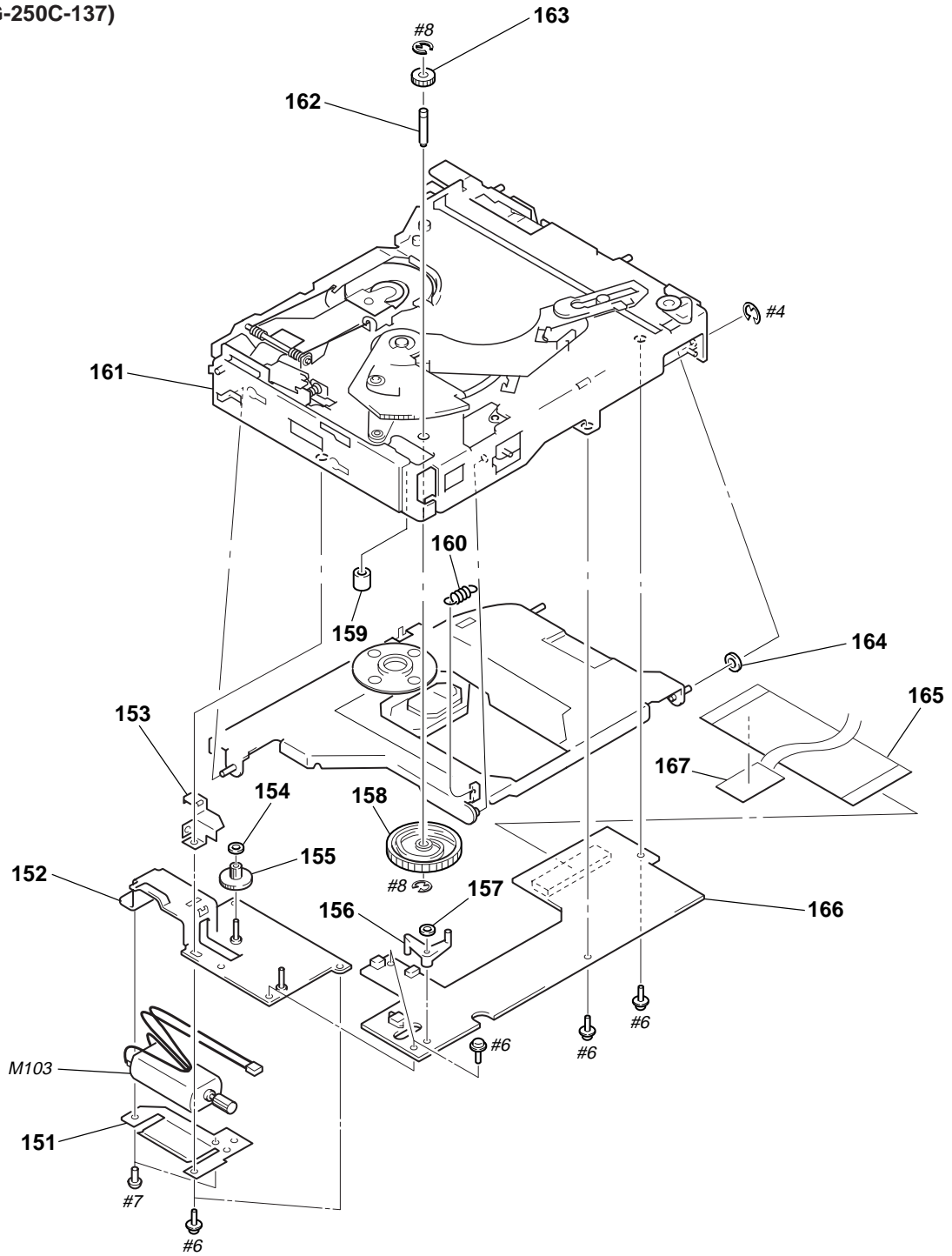
<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remark</u>	<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remark</u>
51	X-3375-497-1	CHASSIS (U) SUB ASSY		53	4-965-759-01	WASHER, POLYETHYLENE	
52	3-024-161-01	SPRING (SUT)		54	3-011-997-01	SPRING (STOPPER. LOWER)	

**(3) MECHANISM DECK SECTION-2
(MG-250C-137)**



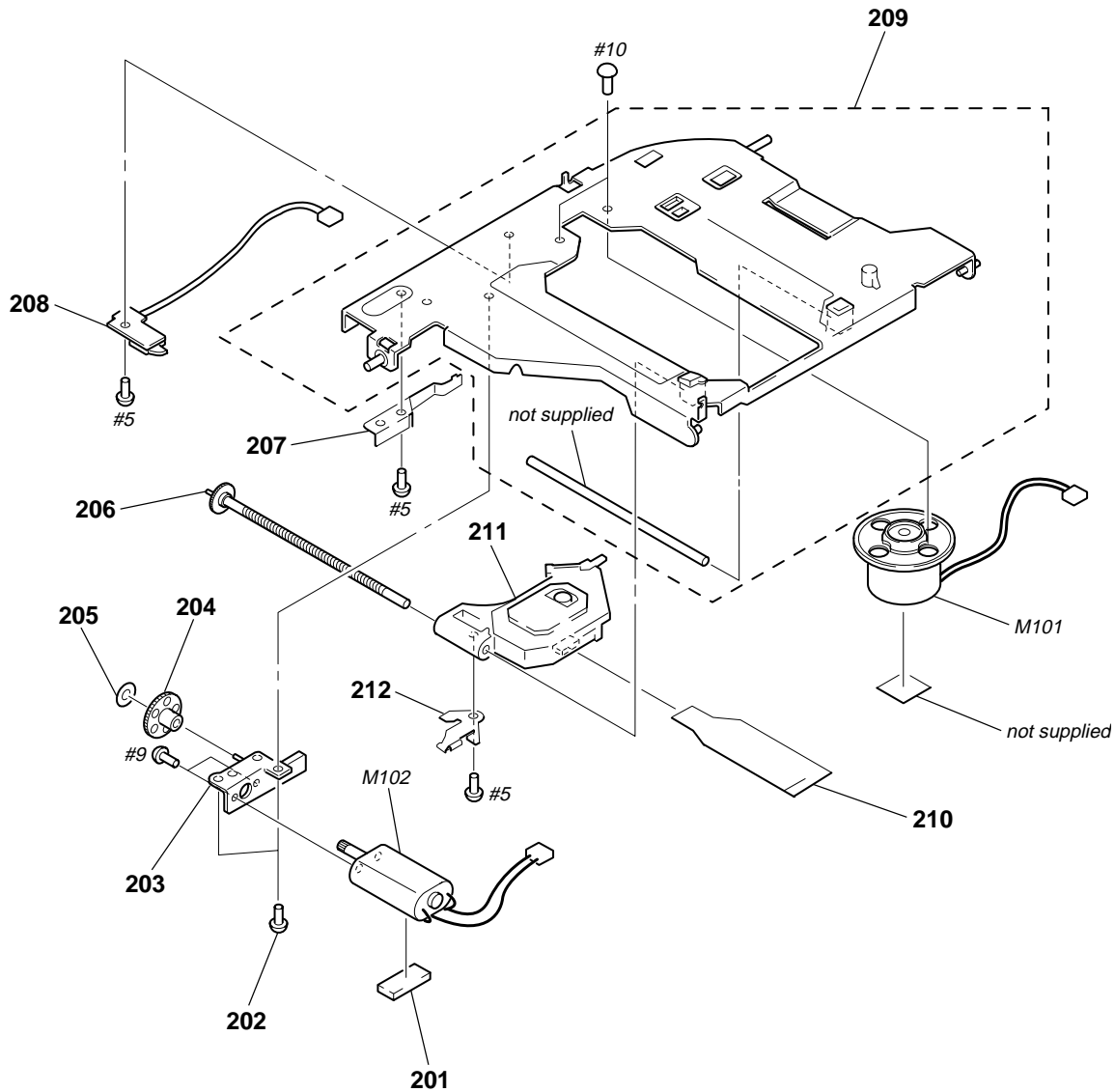
<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remark</u>	<u>Ref. No.</u>	<u>Part No.</u>	<u>Description</u>	<u>Remark</u>
101	3-024-170-01	SPRING (SB), TENSION		103	X-3375-498-1	CHASSIS (D) SUB ASSY	
* 102	3-024-172-01	BRACKET (EVM)		M104	A-3301-123-A	ELJ MOTOR ASSY (ELEVATOR)	

(4) MECHANISM DECK SECTION-3
(MG-250C-137)



Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
* 151	3-024-150-01	RETAINER (CHM)		160	3-010-268-01	SPRING (DH), TENSION	
* 152	X-3375-445-1	BRACKET (CHM) ASSY		* 161	A-3290-194-D	CHASSIS (EVY) (MAIN) ASSY	
153	3-010-270-01	COVER (CHM)		162	3-010-254-01	SHAFT (ROTARY PREVENTION C)	
154	3-321-813-01	WASHER, COTTER POLYETHYLENE		163	3-010-253-01	GEAR (LOMINI)	
155	3-017-139-01	GEAR (WORM LOAD A)		164	3-701-438-11	WASHER, 2.5	
156	3-010-255-01	ARM (LSW)		165	1-664-627-11	MAIN FLEXIBLE BOARD	
157	3-573-936-00	STOPPER, REEL		* 166	A-3313-586-A	RF BOARD, COMPLETE	
158	X-3373-552-1	GEAR (LOAD 1) ASSY		167	3-911-215-02	SHEET (LEAD RETAINER)	
159	3-010-252-01	ROLLER (CRE)		M103	A-3291-953-A	MOTOR ASSY, EL (CHUCKING)	

**(5) MECHANISM DECK SECTION-4
(MG-250C-137)**



The components identified by mark \triangle or dotted line with mark \triangle are critical for safety. Replace only with part number specified.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
201	3-911-215-02	SHEET (LEAD RETAINER)		* 208	1-664-104-11	SW BOARD	
202	3-920-362-01	SCREW (ESCUTCHEON)		* 209	A-3301-077-A	BASE (OPT) (J) ASSY	
203	X-3373-229-1	BASE (SLED) ASSY		210	1-664-626-11	OP FLEXIBLE BOARD	
204	3-010-258-01	GEAR (SLED MID)		\triangle 211	8-820-010-05	OPTICAL PICK-UP KSS-521A/J2RP	
205	3-573-936-00	STOPPER, REEL		212	3-010-262-01	DETENT (SLED)	
206	A-3291-958-A	SHAFT (SLED) ASSY		M101	A-3291-956-A	MOTOR SUB ASSY, SPINDLE	
207	3-010-263-01	DETENT (SHAFT THRUST)		M102	A-3291-955-A	MOTOR SUB ASSY, SLED	

SECTION 9 ELECTRICAL PARTS LIST

JACK	MAIN
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NOTE:

- Due to standardization, replacements in the parts list may be different from the parts specified in the diagrams or the components used on the set.
- -XX and -X mean standardized parts, so they may have some difference from the original one.
- RESISTORS
All resistors are in ohms.
METAL: Metal-film resistor.
METAL OXIDE: Metal oxide-film resistor.
F: nonflammable

- Items marked "*" are not stocked since they are seldom required for routine service. Some delay should be anticipated when ordering these items.
- SEMICONDUCTORS
In each case, u: μ , for example:
uA. . . : μ A. . . uPA. . . : μ PA. . .
uPB. . . : μ PB. . . uPC. . . : μ PC. . .
uPD. . . : μ PD. . .
- CAPACITORS
uF: μ F
- COILS
uH: μ H

The components identified by mark Δ or dotted line with mark Δ are critical for safety. Replace only with part number specified.

When indicating parts by reference number, please include the board.

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
*	1-664-631-15	JACK BOARD *****		C125	1-163-009-11	CERAMIC CHIP 0.001uF 10%	50V
		< CAPACITOR >		C201	1-124-589-11	ELECT 47uF 20%	16V
C901	1-163-009-11	CERAMIC CHIP 0.001uF	10% 50V	C202	1-126-513-11	ELECT 47uF 20%	6.3V
C902	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C203	1-163-038-00	CERAMIC CHIP 0.1uF	25V
C903	1-163-009-11	CERAMIC CHIP 0.001uF	10% 50V	C204	1-115-466-11	ELECT 1000uF 20%	16V
		< CONNECTOR >		C205	1-163-038-00	CERAMIC CHIP 0.1uF	25V
CN901	1-779-077-41	PLUG, CONNECTOR (SONY BUS, AUDIO OUT)		C206	1-124-589-11	ELECT 47uF 20%	16V
CNJ901	1-778-775-21	CONNECTOR, FPC 13P		C207	1-124-589-11	ELECT 47uF 20%	16V
		< FERRITE BEAD >		C208	1-164-346-11	CERAMIC CHIP 1uF	16V
FB901	1-500-445-21	FERRITE 0uH		C209	1-124-589-11	ELECT 47uF 20%	16V
FB902	1-500-445-21	FERRITE 0uH		C210	1-125-701-11	DOUBLE LAYER 0.047F	5.5V
FB903	1-500-445-21	FERRITE 0uH		C211	1-163-038-00	CERAMIC CHIP 0.1uF	25V
		< IC LINK >		C212	1-164-346-11	CERAMIC CHIP 1uF	16V
IC901	1-532-686-21	LINK, IC		C213	1-164-346-11	CERAMIC CHIP 1uF	16V

*	A-3317-257-A	MAIN BOARD, COMPLETE *****		C214	1-163-038-00	CERAMIC CHIP 0.1uF	25V
				C302	1-163-038-00	CERAMIC CHIP 0.1uF	25V
*	3-022-694-01	HOLDER (TR3)		C303	1-126-513-11	ELECT 47uF 20%	6.3V
*	3-016-116-01	TAPE (D), MOUNT		C304	1-163-038-00	CERAMIC CHIP 0.1uF	25V
		< CAPACITOR >		C305	1-163-038-00	CERAMIC CHIP 0.1uF	25V
C101	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C306	1-163-038-00	CERAMIC CHIP 0.1uF	25V
C102	1-163-251-11	CERAMIC CHIP 100PF 5%	50V	C308	1-163-038-00	CERAMIC CHIP 0.1uF	25V
C103	1-163-011-11	CERAMIC CHIP 0.0015uF 10%	50V	C401	1-124-589-11	ELECT 47uF 20%	16V
C104	1-163-809-11	CERAMIC CHIP 0.047uF 10%	25V	C402	1-163-038-00	CERAMIC CHIP 0.1uF	25V
C105	1-164-004-11	CERAMIC CHIP 0.1uF 10%	25V	C403	1-163-038-00	CERAMIC CHIP 0.1uF	25V
C106	1-164-182-11	CERAMIC CHIP 0.0033uF 10%	50V	C404	1-126-513-11	ELECT 47uF 20%	6.3V
C107	1-163-021-11	CERAMIC CHIP 0.01uF 10%	50V	C405	1-126-513-11	ELECT 47uF 20%	6.3V
C108	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C406	1-163-038-00	CERAMIC CHIP 0.1uF	25V
C109	1-126-513-11	ELECT 47uF 20%	6.3V	C407	1-126-157-11	ELECT 10uF 20%	16V
C110	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C408	1-163-038-00	CERAMIC CHIP 0.1uF	25V
C111	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C409	1-126-513-11	ELECT 47uF 20%	6.3V
C120	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C410	1-126-157-11	ELECT 10uF 20%	16V
C121	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C411	1-126-157-11	ELECT 10uF 20%	16V
C122	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C412	1-163-009-11	CERAMIC CHIP 0.001uF 10%	50V
C123	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C413	1-163-251-11	CERAMIC CHIP 100PF 5%	50V
C124	1-163-038-00	CERAMIC CHIP 0.1uF	25V	C414	1-163-251-11	CERAMIC CHIP 100PF 5%	50V
				C415	1-163-259-11	CERAMIC CHIP 220PF 5%	50V
				C501	1-163-009-11	CERAMIC CHIP 0.001uF 10%	50V
				C502	1-163-029-11	CERAMIC CHIP 0.0047uF	50V
				C503	1-163-038-00	CERAMIC CHIP 0.1uF	25V
				C801	1-104-823-11	TANTAL. CHIP 47uF 20%	16V
				C802	1-163-263-11	CERAMIC CHIP 330PF 5%	50V
				C803	1-163-259-11	CERAMIC CHIP 220PF 5%	50V
				C804	1-163-038-00	CERAMIC CHIP 0.1uF	25V
				C805	1-163-009-11	CERAMIC CHIP 0.001uF 10%	50V

MAIN

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
C806	1-164-161-11	CERAMIC CHIP	0.0022uF 10% 100V	Q404	8-729-015-39	TRANSISTOR	DTC323TK
C807	1-163-009-11	CERAMIC CHIP	0.001uF 10% 50V			< RESISTOR >	
C808	1-162-286-21	CERAMIC	220PF F 10% 50V				
C809	1-162-302-11	CERAMIC	0.0022uF 30% 16V	R101	1-216-119-00	METAL CHIP	820K 5% 1/10W
		< CONNECTOR >		R102	1-216-105-00	RES, CHIP	220K 5% 1/10W
CNJ101	1-770-351-11	CONNECTOR, FPC 26P		R103	1-216-073-00	METAL CHIP	10K 5% 1/10W
CNJ201	1-770-350-21	CONNECTOR, FPC 13P		R104	1-216-061-00	METAL CHIP	3.3K 5% 1/10W
CNP301	1-580-055-21	PIN, CONNECTOR 2P		R105	1-216-061-00	METAL CHIP	3.3K 5% 1/10W
		< DIODE >		R106	1-216-073-00	METAL CHIP	10K 5% 1/10W
D201	8-719-210-33	DIODE EC10DS2		R108	1-216-295-00	SHORT	0
D202	8-719-210-33	DIODE EC10DS2		R201	1-216-073-00	METAL CHIP	10K 5% 1/10W
D203	8-719-801-78	DIODE 1SS184		R202	1-216-049-11	RES, CHIP	1K 5% 1/10W
D204	8-719-422-64	DIODE MA8062-M		R203	1-216-089-00	RES, CHIP	47K 5% 1/10W
D205	8-719-038-48	DIODE 1SS319 (TE85R)		R204	1-216-097-00	RES, CHIP	100K 5% 1/10W
D206	8-719-801-78	DIODE 1SS184		R205	1-216-077-00	METAL CHIP	15K 5% 1/10W
D207	8-719-422-62	DIODE MA8062-L-TX		R206	1-216-057-00	METAL CHIP	2.2K 5% 1/10W
D301	8-719-801-78	DIODE 1SS184		R207	1-216-089-00	RES, CHIP	47K 5% 1/10W
D311	8-719-975-40	DIODE RB411D		R208	1-216-689-11	METAL CHIP	39K 0.5% 1/10W
D501	8-719-422-62	DIODE MA8062-L-TX		R301	1-216-065-00	RES, CHIP	4.7K 5% 1/10W
D502	8-719-975-40	DIODE RB411D		R302	1-216-089-00	RES, CHIP	47K 5% 1/10W
D503	8-719-975-40	DIODE RB411D		R303	1-216-065-00	RES, CHIP	4.7K 5% 1/10W
D504	8-719-422-62	DIODE MA8062-L-TX		R304	1-216-089-00	RES, CHIP	47K 5% 1/10W
D505	8-719-975-40	DIODE RB411D		R305	1-216-089-00	RES, CHIP	47K 5% 1/10W
		< FERRITE BEAD >		R306	1-216-089-00	RES, CHIP	47K 5% 1/10W
FB101	1-500-445-21	FERRITE	0uH	R307	1-216-089-00	RES, CHIP	47K 5% 1/10W
FB102	1-500-445-21	FERRITE	0uH	R308	1-216-089-00	RES, CHIP	47K 5% 1/10W
FB103	1-500-445-21	FERRITE	0uH	R310	1-216-089-00	RES, CHIP	47K 5% 1/10W
FB111	1-216-295-00	SHORT	0	R311	1-216-089-00	RES, CHIP	47K 5% 1/10W
FB112	1-216-295-00	SHORT	0	R312	1-216-065-00	RES, CHIP	4.7K 5% 1/10W
FB401	1-500-445-21	FERRITE	0uH	R313	1-216-097-00	RES, CHIP	100K 5% 1/10W
FB411	1-216-295-00	SHORT	0	R318	1-216-033-00	METAL CHIP	220 5% 1/10W
FB412	1-216-295-00	SHORT	0	R319	1-216-089-00	RES, CHIP	47K 5% 1/10W
FB413	1-216-295-00	SHORT	0	R320	1-216-065-00	RES, CHIP	4.7K 5% 1/10W
FB414	1-216-295-00	SHORT	0	R321	1-216-073-00	METAL CHIP	10K 5% 1/10W
		< IC >		R331	1-216-097-00	RES, CHIP	100K 5% 1/10W
IC101	8-752-384-15	IC CXD2530Q		R332	1-216-089-00	RES, CHIP	47K 5% 1/10W
IC102	8-759-537-11	IC SM5852FS-E2		R333	1-216-295-00	SHORT	0
IC201	8-759-054-12	IC PQ09RA1		R334	1-216-295-00	SHORT	0
IC202	8-759-443-41	IC RH5VL40AA-T1C		R335	1-216-295-00	SHORT	0
IC203	8-759-324-40	IC KIA7805PI		R343	1-216-073-00	METAL CHIP	10K 5% 1/10W
IC204	8-759-444-86	IC BA8272F-E2		R401	1-216-033-00	METAL CHIP	220 5% 1/10W
IC301	8-759-040-83	IC BA6287F		R405	1-216-033-00	METAL CHIP	220 5% 1/10W
IC302	8-752-898-75	IC CXP84124-078Q		R406	1-216-033-00	METAL CHIP	220 5% 1/10W
IC401	8-759-494-78	IC TC9464FN-EL		R407	1-216-097-00	RES, CHIP	100K 5% 1/10W
		< TRANSISTOR >		R408	1-216-097-00	RES, CHIP	100K 5% 1/10W
Q201	8-729-016-83	TRANSISTOR	2SB1446	R411	1-216-029-00	METAL CHIP	150 5% 1/10W
Q202	8-729-901-00	TRANSISTOR	DTC124EK	R501	1-216-089-00	RES, CHIP	47K 5% 1/10W
Q203	8-729-230-49	TRANSISTOR	2SC2712-YG			< VARIABLE RESISTOR >	
Q204	8-729-027-31	TRANSISTOR	DTA124EKA-T146	RV301	1-223-834-11	RES, ADJ, CARBON	47K
Q205	8-729-822-05	TRANSISTOR	2SD1622-ST-TD	RV302	1-225-412-11	RES, VAR, SLIDE	10K (ELEVATOR HEIGHT SENSOR)
Q301	8-729-020-67	TRANSISTOR	XN1A312-TX			< SWITCH >	
Q401	8-729-901-00	TRANSISTOR	DTC124EK	SW301	1-762-108-31	SWITCH, PUSH (1 KEY)	(MAGAZINE EJECT END DETECT)
Q402	8-729-027-23	TRANSISTOR	DTA114EKA-T146	SW302	1-762-108-31	SWITCH, PUSH (1 KEY)	(MAGAZINE IN/OUT DETECT)
Q403	8-729-015-39	TRANSISTOR	DTC323TK				

Ref. No.	Part No.	Description	Remark	Ref. No.	Part No.	Description	Remark
SW303	1-571-532-21	SWITCH, TACTIL (▲)		CNP51	1-580-055-21	PIN, CONNECTOR 2P	
		< VIBRATOR >		CNP52	1-580-055-21	PIN, CONNECTOR 2P	
X301	1-767-261-21	VIBRATOR, CERAMIC (8MHz)		CNP53	1-580-055-21	PIN, CONNECTOR 2P	
X401	1-767-511-11	VIBRATOR, CERAMIC (16.930MHz)				< IC >	

*	A-3313-586-A	RF BOARD, COMPLETE		IC11	8-752-082-14	IC CXA1992BR	
		*****		IC51	8-759-071-79	IC BA6297AFP	
		< CAPACITOR >		IC52	8-759-040-83	IC BA6287F	
C10	1-163-009-11	CERAMIC CHIP	0.001uF 10% 50V			< TRANSISTOR >	
C12	1-113-500-11	TANTAL. CHIP	100uF 20% 10V	Q11	8-729-141-48	TRANSISTOR 2SB624-BV345	
C13	1-163-038-00	CERAMIC CHIP	0.1uF 25V			< RESISTOR >	
C14	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	R11	1-216-844-11	METAL CHIP 82K 5% 1/16W	
C15	1-162-957-11	CERAMIC CHIP	220PF 5% 50V	R12	1-216-839-11	METAL CHIP 33K 5% 1/16W	
C16	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V	R13	1-216-839-11	METAL CHIP 33K 5% 1/16W	
C17	1-164-227-11	CERAMIC CHIP	0.022uF 10% 25V	R14	1-216-844-11	METAL CHIP 82K 5% 1/16W	
C18	1-111-253-11	TANTAL. CHIP	100uF 20% 6.3V	R16	1-216-857-11	METAL CHIP 1M 5% 1/16W	
C19	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R17	1-216-837-11	METAL CHIP 22K 5% 1/16W	
C21	1-162-966-11	CERAMIC CHIP	0.0022uF 10% 50V	R18	1-216-841-11	METAL CHIP 47K 5% 1/16W	
C22	1-107-823-11	CERAMIC CHIP	0.47uF 10% 16V	R22	1-216-857-11	METAL CHIP 1M 5% 1/16W	
C23	1-113-682-11	TANTAL. CHIP	33uF 20% 10V	R25	1-216-851-11	METAL CHIP 330K 5% 1/16W	
C24	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V	R26	1-216-845-11	METAL CHIP 100K 5% 1/16W	
C25	1-107-826-11	CERAMIC CHIP	0.1uF 10% 16V	R27	1-216-295-00	SHORT 0	
C26	1-164-232-11	CERAMIC CHIP	0.01uF 50V	R28	1-216-295-00	SHORT 0	
C27	1-164-677-11	CERAMIC CHIP	0.033uF 10% 16V	R30	1-216-829-11	METAL CHIP 4.7K 5% 1/16W	
C28	1-164-245-11	CERAMIC CHIP	0.015uF 10% 25V	R31	1-216-829-11	METAL CHIP 4.7K 5% 1/16W	
C29	1-165-176-11	CERAMIC CHIP	0.047uF 10% 16V	R32	1-216-837-11	METAL CHIP 22K 5% 1/16W	
C30	1-162-970-11	CERAMIC CHIP	0.01uF 10% 25V	R33	1-216-158-00	RES, CHIP 22 5% 1/8W	
C31	1-113-987-11	TANTAL. CHIP	4.7uF 20% 25V	R34	1-216-855-11	METAL CHIP 680K 5% 1/16W	
C32	1-164-677-11	CERAMIC CHIP	0.033uF 10% 16V	R35	1-216-835-11	METAL CHIP 15K 5% 1/16W	
C33	1-162-915-11	CERAMIC CHIP	10PF 0.5PF 50V	R36	1-216-836-11	METAL CHIP 18K 5% 1/16W	
C34	1-162-970-11	CERAMIC CHIP	0.01uF 10% 25V	R37	1-216-851-11	METAL CHIP 330K 5% 1/16W	
C35	1-104-700-11	CERAMIC CHIP	0.027uF 10% 16V	R38	1-216-837-11	METAL CHIP 22K 5% 1/16W	
C36	1-162-970-11	CERAMIC CHIP	0.01uF 10% 25V	R39	1-216-847-11	METAL CHIP 150K 5% 1/16W	
C37	1-109-982-11	CERAMIC CHIP	1uF 10% 10V	R40	1-218-273-11	RES, CHIP 510K 5% 1/16W	
C38	1-104-913-11	TANTAL. CHIP	10uF 20% 16V	R41	1-218-296-11	RES, CHIP 75K 5% 1/16W	
C39	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R42	1-202-930-11	RES, CHIP 750K 5% 1/16W	
C40	1-109-982-11	CERAMIC CHIP	1uF 10% 10V	R43	1-216-849-11	METAL CHIP 220K 5% 1/16W	
C41	1-164-227-11	CERAMIC CHIP	0.022uF 10% 25V	R44	1-216-846-11	METAL CHIP 120K 5% 1/16W	
C42	1-164-227-11	CERAMIC CHIP	0.022uF 10% 25V	R45	1-216-837-11	METAL CHIP 22K 5% 1/16W	
C43	1-164-227-11	CERAMIC CHIP	0.022uF 10% 25V	R46	1-216-847-11	METAL CHIP 150K 5% 1/16W	
C51	1-163-019-00	CERAMIC CHIP	0.0068uF 10% 50V	R47	1-216-834-11	METAL CHIP 12K 5% 1/16W	
C52	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R48	1-216-845-11	METAL CHIP 100K 5% 1/16W	
C53	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R49	1-216-093-00	METAL CHIP 68K 5% 1/10W	
C54	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R50	1-216-841-11	METAL CHIP 47K 5% 1/16W	
C55	1-163-023-00	CERAMIC CHIP	0.015uF 5% 50V	R51	1-216-073-00	METAL CHIP 10K 5% 1/10W	
C56	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R52	1-216-093-00	METAL CHIP 68K 5% 1/10W	
C57	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R53	1-216-073-00	METAL CHIP 10K 5% 1/10W	
C58	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R54	1-216-073-00	METAL CHIP 10K 5% 1/10W	
C59	1-163-038-00	CERAMIC CHIP	0.1uF 25V	R55	1-216-073-00	METAL CHIP 10K 5% 1/10W	
C60	1-104-914-11	TANTAL. CHIP	22uF 20% 16V	R56	1-216-093-00	METAL CHIP 68K 5% 1/10W	
		< CONNECTOR >		R57	1-216-081-00	METAL CHIP 22K 5% 1/10W	
CNJ11	1-778-776-21	CONNECTOR, FPC 17P		R58	1-216-093-00	METAL CHIP 68K 5% 1/10W	
CNJ12	1-778-777-21	CONNECTOR, FPC 26P		R59	1-216-073-00	METAL CHIP 10K 5% 1/10W	
CNP11	1-580-055-21	PIN, CONNECTOR 2P		R60	1-216-073-00	METAL CHIP 10K 5% 1/10W	
				R61	1-216-073-00	METAL CHIP 10K 5% 1/10W	

CDX-605

RF **SW**

Ref. No.	Part No.	Description	Remark
R62	1-216-085-00	METAL CHIP 33K 5%	1/10W
R63	1-216-073-00	METAL CHIP 10K 5%	1/10W
R64	1-216-073-00	METAL CHIP 10K 5%	1/10W
R65	1-216-073-00	METAL CHIP 10K 5%	1/10W
		< VARIABLE RESISTOR >	
RV14	1-238-091-11	RES, ADJ, CERMET 22K	
		< SWITCH >	
SW11	1-762-946-11	SWITCH, PUSH (1 KEY) (CHUCKING END DETECT)	
SW12	1-762-946-11	SWITCH, PUSH (1 KEY) (SAVE END DETECT)	

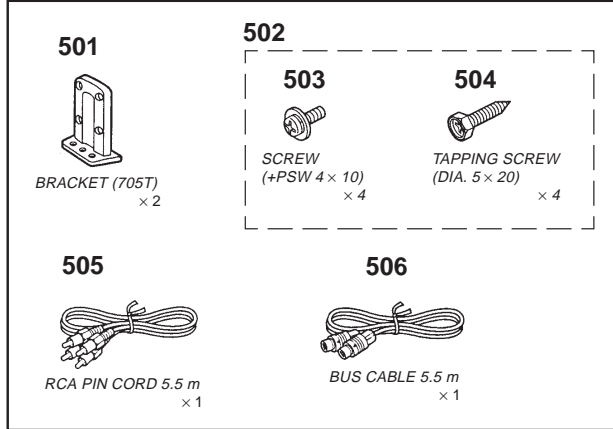
*	1-664-104-11	SW BOARD *****	
		< SWITCH >	
SW1	1-572-688-11	SWITCH, PUSH (1 KEY) (LIMIT)	

		MISCELLANEOUS *****	
3	1-664-628-11	JACK FLEXIBLE BOARD	
165	1-664-627-11	MAIN FLEXIBLE BOARD	
210	1-664-626-11	OP FLEXIBLE BOARD	
△211	8-820-010-05	OPTICAL PICK-UP KSS-521A/J2RP	
M101	A-3291-956-A	MOTOR SUB ASSY, SPINDLE	
M102	A-3291-955-A	MOTOR SUB ASSY, SLED	
M103	A-3291-953-A	MOTOR ASSY, EL (CHUCKING)	
M104	A-3301-123-A	ELJ MOTOR ASSY (ELEVATOR)	

		HARDWARE LIST *****	
#1	7-627-852-07	SCREW, PRECISION +P 1.7X2.5	
#2	7-685-792-09	SCREW +PTT 2.6X6 (S)	
#3	7-685-781-09	SCREW +PTT 2X4 (S)	
#4	7-624-104-04	STOP RING 2.0, TYPE-E	
#5	7-627-554-07	SCREW, PRECISION +P 2X2.2	
#6	7-628-253-00	SCREW +PS 2X4	
#7	7-627-553-27	SCREW, PRECISION +P 2X2.5	
#8	7-624-102-04	STOP RING 1.5, TYPE-E	
#9	7-627-850-28	SCREW, PRECISION +P 1.4X3	
#10	7-627-000-00	SCREW, PRECISION +P 1.7X2.2 TYPE3	
#11	7-685-851-04	SCREW +BVTT 2X4 (S)	

		ACCESSORIES & PACKING MATERIALS *****	
	3-862-311-31	MANUAL, INSTRUCTION (ENGLISH, FRENCH, SPANISH, CHINESE)	
	A-3291-950-D	MAGAZINE (250T) ASSY	

Ref. No.	Part No.	Description	Remark
		PARTS FOR INSTALLATION AND CONNECTIONS *****	
501	3-022-693-01	BRACKET (705T)	
* 502	X-3369-824-1	SCREW ASSY	
503	7-682-962-01	SCREW +PSW 4X10	
504		Not supplied	
505	1-590-874-11	CORD, CONNECTION (RCA PIN CORD 5.5m)	
506	1-590-519-81	CORD (WITH CONNECTOR) (BUS CABLE 5.5m)	



The components identified by mark △ or dotted line with mark △ are critical for safety. Replace only with part number specified.